

现场活动一览 Onsite Events

 具身智能 / Embodied AI		
2026 具身智能技术创新与供应链协同论坛 2026 Embodied Intelligence Technology Innovation and Supply Chain Synergy Forum	10:00-16:30	7 号馆, 7F90, 具身智能剧院 1 7F90, Embodied Intelligence Theatre 1, Hall 7
2026 具身机器人工业智造升级论坛 2026 Embodied Robotics Forum for Smart Manufacturing Industrial Upgrade	10:00-12:00	7 号馆, 7A90, 具身智能剧院 2 7A90, Embodied Intelligence Theatre 2, Hall 7
2026 具身机器人商用服务落地论坛 2026 Embodied Robotics Forum for Commercial Service Deployment	13:30-15:00	7 号馆, 7A90, 具身智能剧院 2 7A90, Embodied Intelligence Theatre 2, Hall 7
2026 具身机器人特种极限作业论坛 2026 Embodied Robotics Forum for Special Purpose Extreme Environment Operations	15:00-17:00	7 号馆, 7A90, 具身智能剧院 2 7A90, Embodied Intelligence Theatre 2, Hall 7
工厂参观 - 非夕机器人 Factory Visit - Flexiv	15:00-18:20	
擎天租智能机器人嘉年华 Sharebot Robotech Carnival	09:30-17:00	7 号馆, 7M90&7J90, 擎天租智能机器人嘉年华 Hall 7 7M90&7J90 Sharebot Robotech Carnival
 电子元器件 / Electronic Components		
“芯”选型·车智联·国产芯——元器件供应链、汽车电子与端侧 AI 技术应用论坛 “Chip” Selection · Vehicle Intelligence Connectivity · Domestic Chips - Forum on Component Supply Chain, Automotive Electronics, and Edge AI Technology Applications	10:00-12:00	15 号馆, 一号会议室 Conference Room 1, Hall 15
第二届国产芯片技术创新与市场应用论坛 The 2 nd Domestic Chip Technology Innovation and Market Application Forum	13:00-16:40	15 号馆, 一号会议室 Conference Room 1, Hall 15
芜湖电子产业交流会 Wuhu Electronics Industry Forum	10:00-12:30	15 号馆, 二号会议室 Conference Room 2, Hall 15
数据驱动·AI 赋能——电子元器件原厂竞争力重构创新论坛 Data-Driven · AI-Empowered - Innovation Forum on Restructuring the Competitiveness of Electronic Component Original Manufacturers	14:00-17:00	15 号馆, 二号会议室 Conference Room 2, Hall 15
2026 汽车电子与电源专场采购对接会 2026 Automotive Electronics & Power Supply Special Procurement Matchmaking Conference	10:00-12:00	15 号馆, 国内采购对接区 Hall 15, Domestic Procurement Matching Zone

10.28.2026 星期三 / Wednesday

会议名称 / Conference Name	时间 / Time	地点 / Location
 电子制造 / Electronics Manufacturing		
 SMTA 华南高科技设备研讨会 SMTA China South Vendor Conference	11:00-14:30	11 号馆, 11G65 展位 11G65, Hall 11
 SMTA 华南国际论坛 2026 SMTA South China International Forum 2026	13:30-15:30	9/11 号馆 (二层), 9 号会议室 9-C Meeting Room 9-C, Halls 9/11 (Level 2)
2026 (第二十八届) 深圳智能制造及 SMT 技术高级研讨会 2026 (The 28 th) Shenzhen IMT&SMT High-level Conference	10:00-16:10	9 号馆, NEPCON 剧院, 9H100 9H100, NEPCON Theatre, Hall 9
第六届“弘快杯”全国电子制造行业 PCB 设计大赛总决赛 The 6 th “Hongkuai Cup” National Electronics Manufacturing Industry PCB Design Competition Grand Final	09:00-16:30	15 号馆, 竞技场 1, 15A100 15A100, Arena 1, Hall 15

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现场活动一览 Onsite Events

第三届“ESAMBER 屹博杯”全国电子制造行业板级故障分析与维修技能大赛总决赛（实操） The 3 rd “ESAMBER Yibo Cup” National Electronics Manufacturing Industry Board-Level Failure Analysis and Repair Skills Competition Grand Final (Practical)		09:00-16:10	15 号馆, 竞技场 2, 15C100 15C100, Arena 2, Hall 15
《线束线缆组装技术》高级培训 Advanced Training on Wire Harness & Cable Assembly Technology		09:30-16:30	15 号馆, 竞技场 3, 15F100 15F100, Arena 3, Hall 15
光模块 / Optical Module			
光通信先进制造技术创新高峰论坛 2026 Advanced Optical Communication Manufacturing Technology Innovation Summit		13:30-16:30	13 号馆, 光通信剧院, 13F10 13F10, Optical Communications Theatre, Hall 13
绿色工厂 & 工厂设施 / Green Factory & Factory Facilities			
绿色智能工厂设施大会 Green & Smart Factory Facilities Conference		10:00-12:10	9 号馆, 绿色智造剧院, 9D90 9D90, Green Smart Manufacturing Theatre, Hall 9
2026 深圳电子工厂节能降碳技术研讨会 2026 Shenzhen Electronics Factory Energy-Saving & Carbon-Reduction Technology Seminar		13:30-15:55	9 号馆, 绿色智造剧院, 9D90 9D90, Green Smart Manufacturing Theatre, Hall 9
算力 / Computational Power			
2026 智算生态大会——AI 算力场景应用与产业融合·智算中心与工业场景应用论坛 2026 Smart Computing Ecosystem Conference - Intelligent Computing Center & Industrial Scenarios Forum		10:00-15:50	15 号馆, 1 号会议室 Conference Room 1, Hall 15
汽车电子 / Automotive Electronics			
智能汽车“百家论坛”第三十期 AWC 破卷突围—AI 驱动汽车升级的产业需求与机遇 Intelligent Vehicle Forum: Industrial Demands and Opportunities in AI-Driven Automotive Upgrades		14:00-16:40	13 号馆, 13G30, AWC 剧院 13G30, AWC Theater, Hall 13
AWC—深圳市汽车电子行业协会专场采购配对会 Shenzhen Automotive Electronics Industry Association Special Procurement Matchmaking Conference		上午	13 号馆, AWC 剧院 AWC Theatre, Hall 13
机器视觉 / Machine Vision			
深圳机器视觉展暨机器视觉技术及工业应用研讨会 Shenzhen Machine Vision Exhibition And Machine Vision Technology&Application Conference		09:30-17:00	9 号馆, 9F66 9F66, Hall 9
具身智能 / Embodied AI			
2026 具身智能产业趋势与产品能力升级论坛 2026 Embodied Intelligence Forum for Industry Trends & Product Performance Upgrade		10:00-16:30	7 号馆, 7F90, 具身智能剧院 1 7F90, Embodied Intelligence Theatre 1, Hall 7
2026 粤港澳大湾区机器人创新技术论坛暨粤港澳大湾区机器人科技杰出贡献评选颁奖典礼 2026 GBA Robot Innovation Technology Forum & Award Ceremony for GBA Robot Technology Outstanding Contribution		10:00-12:35	7 号馆, 7A90, 具身智能剧院 2 7A90, Embodied Intelligence Theatre 2, Hall 7
擎天租智能机器人嘉年华 Sharebot Robotech Carnival		09:30-17:00	7 号馆, 7M90&7J90, 擎天租智能机器人嘉年华 Hall 7 7M90&7J90 Sharebot Robotech Carnival

现场活动一览 Onsite Events



电子元器件 / Electronic Components



AI 算力及液冷技术生态合作大会

AI Computing Power and Liquid Cooling Technology Ecosystem Cooperation Conference

10:30-12:30

15 号馆, 二号会议室
Hall 15, Meeting Room 2

10.29.2026 星期四 / Thursday

会议名称 / Conference Name

时间 / Time

地点 / Location



电子制造 / Electronics Manufacturing



第六届“弘快杯”全国电子制造行业 PCB 设计大赛总决赛

The 6th "Hongkuai Cup" National Electronics Manufacturing Industry PCB Design Competition Grand Final

09:30-11:30

15 号馆, 竞技场 1, 15A100
15A100, Arena 1, Hall 15

第三届“ESAMBER 屹博杯”全国电子制造行业板级故障分析与维修技能大赛总决赛 (答辩)

The 3rd "ESAMBER Yibo Cup" National Electronics Manufacturing Industry Board-Level Failure Analysis and Repair Skills Competition Grand Final (Defense)

09:00-12:30

15 号馆, 竞技场 2, 15C100
15C100, Arena 2, Hall 15

第四届“智汇杯”全国电子制造行业线束线缆制作工艺与操作技能大赛总决赛 (答辩)

The 4th "Zhihui Cup" National Electronics Manufacturing Industry Wire Harness & Cable Fabrication Process and Operation Skills Competition Grand Final (Defense)

09:00-12:00

15 号馆, 竞技场 3, 15F100
15F100, Arena 3, Hall 15



算力 / Computational Power



2026 AI 算力产业生态合作创新 (深圳) 大会

2026 AI Computing Power Industry Ecosystem Cooperation & Innovation (Shenzhen) Conference

10:00-12:10

13 号馆, 光通信剧院, 13F10
13F10, Optical Communications Theatre, Hall 13

NEW



物流仓储 / Logistics & Warehousing



2026 智能仓储及智慧物流技术峰会

2026 Intelligent Warehousing & Smart Logistics Technology Summit

10:00-12:25

9 号馆, 9D90, 绿色智造剧院
9D90, Green Smart Manufacturing Theatre, Hall 9



具身智能 / Embodied AI



2026 具身智能人才培养与产业落地论坛

2026 Embodied Intelligence Talent Development and Industry Implementation Forum

10:00-12:10

7 号馆, 7F90, 具身智能剧院 1
7F90, Embodied Intelligence Theatre 1, Hall 9

工厂参观——东莞市数据标注产业园

Factory Visit - Dongguan Data Annotation Industrial Park

下午

擎天租智能机器人嘉年华

Sharebot Robotech Carnival

09:30-15:30

7 号馆, 7M90&7J90, 擎天租智能
机器人嘉年华
Hall 7 7M90&7J90 Sharebot Robotech
Carnival



电子元器件 / Electronic Components



淮南电子产业交流会

Huainan Electronic Industry Exchange Conference

09:30-12:00

15 号馆, 一号会议室
Hall 15, Meeting Room 1

亚洲工业科技展·蓝点奖颁奖典礼

Industrial Technology World Asia · Blue Dot Awards Ceremony

10:30-12:00

15 号馆, 二号会议室
Hall 15, Meeting Room 2

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研讨会议程 Conference Program

SMTA 华南高科技技术研讨会 SMTA China South Technology Conference



2026 年 10 月 27 日 9/11 号馆 (二层), 9 号会议室 9-C
27th October 2026 Meeting Room 9-C, Halls 9/11 (Level 2)

时间 Time	主题 Topic	演讲嘉宾 Speaker
会议主席 Conference Chairman 董林, 中国 SMTA 技术委员会主席, 捷普电子 (广州) 有限公司制造工程专家 Lin Dong, Chairman of SMTA China Technical Committee, Manufacturing Engineering SME of JABIL CIRCUIT (GUANGZHOU) LIMITED		
10:45 - 11:15	新型超低残留锡膏在系统级封装中的应用 Application of New Ultra-Low Residue Solder Paste for System-In-Package (CS26-TC1.1)	 胡彦杰, 钢泰公司 Leo Hu, Indium Corporation
11:15 - 11:20	有奖抢答 / Prize Quiz	
11:20 - 11:50	电力电子封装中甲酸焊接材料的技术进展 Advancements In Formic Acid Soldering Materials Technology for Power Device Packaging (CS26-TC1.2)	 乔广浩, 钢泰公司 Joey Qiao, Indium Corporation
11:50 - 11:55	有奖抢答 / Prize Quiz	
11:55 - 12:25	利用大语言模型从工业时间序列数据中获取运行洞察 Leveraging Large Language Models for Operational Insights From Industrial Time-Series Data (CS26-TC1.3)	 Sergei Knyazhishche MKS' Atotech 安美特 (中国) 化学有限公司
12:25 - 12:30	有奖抢答 / Prize Quiz	
12:30 - 13:45	午餐 / Lunch Break	
13:45 - 14:15	现代无铅合金格局: 突破 SAC305 的局限 The Modern Lead-Free Alloy Landscape: Moving Beyond SAC305 (CS26-TC1.4)	 姜涛, AIM Solder Diego Jiang, AIM Solder
14:15 - 14:20	有奖抢答 / Prize Quiz	
14:20 - 14:50	相干光模块耦合封装工艺的研究 Challenges In The Coupling and Packaging Process of Coherent Optical Modules (CS26-TC1.5)	 陈达, 中兴通讯股份有限公司 Da Chen, ZTE Corporation
14:50 - 14:55	有奖抢答 / Prize Quiz	
14:55 - 15:25	SMT 产线高效设计方案及实践 (CS26-TC1.6)	 葛文豪, 联合汽车电子有限公司 Wenhao Ge, United Automotive Electronic Systems Co., Ltd.
15:25 - 15:30	有奖抢答 / Prize Quiz	

研讨会议程 Conference Program

SMTA 华南高科技设备研讨会 SMTA China South Vendor Conference



2026 年 10 月 27 日 11 号馆, 11G65 展位
27th October 2026 11G65, Hall 11

时间 Time	主题 Topic	演讲嘉宾 Speaker
会议主席 Conference Chairman 吴明炜, 合肥谱睿源电子有限公司董事长, 中国 SMTA 技术顾问委员会委员 Vincent Wu, Chairman of Imagesource Intelligent Manufacturing HeFei Co., Ltd., Member of SMTA China Technical Advisory Committee		
11:00 - 11:25	闭环清洗技术及应用 Close-Loop Cleaning Technology and Its Application (CS26-VC1.1)	罗盛彪, 深圳市三捷机械设备有限公司 Shengbiao Luo, Shenzhen Synergies Machinery Co., Ltd.
11:25 - 11:30	有奖抢答 / Prize Quiz	
11:30 - 11:55	AI 赋能在线 3D-X 光测试, 破解先进封装多层堆叠缺陷识别难题 Theme: AI-Empowered Inline 3D X-Ray Inspection: Tackling Defect Recognition Challenges of Multi-Layer Stacking In Advanced Packaging (CS26-VC1.2)	吴明炜, 合肥谱睿源智能制造有限公司 Vincent Wu, Imagesource Intelligent Manufacturing HeFei Co., Ltd.
11:55 - 12:00	有奖抢答 / Prize Quiz	
12:00 - 12:25	从 PCBA“0” 废水清洗开始 From PCBA Zero-Wastewater Cleaning Begins (CS26-VC1.3)	姚鑫, 深圳市山木电子设备有限公司 Xin Yao, Shenzhen SAM Electronic Equipment Co., Ltd.
12:25 - 12:30	有奖抢答 / Prize Quiz	
12:30 - 14:00	午餐 / Lunch Break	
14:00 - 14:25	新一代烧录解决方案: 实现良率、生产效率与信息安全三位一体 New-Generation Programming Solution: Achieving The Trinity of Yield, Production Efficiency and Information Security (CS26-VC1.4)	李儒俊, 深圳市昂科技术有限公司 Rujun Li, Shenzhen Acroview Technology Co., Ltd.
14:25 - 14:30	有奖抢答 / Prize Quiz	
14:30 - 14:55	《从工程验证到规模量产: A8100T 三温测试分选平台的全栈能力解读》 From Engineering Validation To Mass-Production: Interpretation of Full-Stack Capabilities of A8100T Three-Temperature Test & Sorting Platform (CS26-VC1.5)	赖雅琪, 深圳市昂科技术有限公司 Yaqi Lai, Shenzhen Acroview Technology Co., Ltd.
14:55 - 15:00	有奖抢答 / Prize Quiz	
15:00 - 15:25	《让 LPDDR 量产更可靠 可落地的 SLT 测试设备验证方案》 Making LPDDR Mass Production More Reliable A Practical Validation Scheme for Burn-In Test Equipment (CS26-VC1.6)	温妍, 深圳市昂科技术有限公司 Yan Wen, Shenzhen Acroview Technology Co., Ltd.
15:25 - 15:30	有奖抢答 / Prize Quiz	

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研讨会议程 Conference Program

SMTA 华南高科技设备研讨会 SMTA China South Vendor Conference



2026 年 10 月 28 日 11 号馆, 11G65 展位
28th October 2026 11G65, Hall 11

时间 Time	主题 Topic	演讲嘉宾 Speaker
会议主席 Conference Chairman 胡彦杰, 镓泰公司中国区技术经理 Leo Hu, Country Technical Manager-China of Indium Corporation		
11:00 - 11:25	AI 与车规时代, 芯片烧录的可靠性与效率革新 AI and Automotive-Grade Era: Innovations In Chip Programming Reliability and Efficiency (CS26-VC2.1)	莫建勋, 深圳市昂科技术有限公司 Jianxun Mo, Shenzhen Acroview Technology Co., Ltd.
11:25 - 11:30	有奖抢答 / Prize Quiz	
11:30 - 11:55	让嵌入式存储稳定量产 面向 eMMC/UFS 的一体化可靠性测试方案 Enabling Stable Mass Production of Embedded Storage Integrated Reliability Test Solution for eMMC/UFS (CS26-VC2.2)	隆凤, 深圳市昂科技术有限公司 Feng Long, Shenzhen Acroview Technology Co., Ltd.
11:55 - 12:00	有奖抢答 / Prize Quiz	
12:00 - 12:25	AI 算力引发的电源老化测试技术革命 The Technological Revolution In Power Aging Testing Triggered By AI computing Power (CS26-VC2.3)	王恒, 深圳市昂科技术有限公司 Heng Wang, Shenzhen Acroview Technology Co., Ltd.
12:25 - 12:30	有奖抢答 / Prize Quiz	
12:30 - 14:00	午餐 / Lunch Break	
14:00 - 14:25	汽车电子 SMT 生产制造智能物流设计及实践 Design and Practice of Intelligent Logistics for Automotive Electronics SMT Manufacturing (CS26-VC2.4)	葛文豪, 联合汽车电子有限公司 Wenhao Ge, United Automotive Electronic Systems Co., Ltd.
14:25 - 14:30	有奖抢答 / Prize Quiz	

研讨会议程 Conference Program

SMTA 华南国际论坛 2026 SMTA South China International Forum 2026



2026 年 10 月 28 日 9/11 号馆 (二层), 9 号会议室 9-C
28th October 2026 Meeting Room 9-C, Halls 9/11 (Level 2)

时间 Time	主题 Topic	演讲嘉宾 Speaker
13:30 - 14:00	TGV 互连失效机理及可靠性研究 Failure Mechanisms and Reliability Study of TGV Interconnections	杨晓锋, 工业和信息化部电子第五研究所; 高级工程师 / 电子元器件可靠性技术全国重点实验室先进封装与微系统可靠性技术总师 Yang Xiaofeng, he Fifth Electronics Research Institute of the Ministry of Industry and Information Technology, Senior Engineer, National Key Laboratory of Reliability Technology for Electronic Components, Chief Engineer of Advanced Packaging & Microsystem Reliability Technology
14:00 - 14:40	用于先进芯粒封装的玻璃芯基板 Glass Core Substrates for Advanced Chip Packaging	拉尔斯·博彻, SMTA 国际会议技术委员会成员、IMAPS 器件封装会议技术主席、德国柏林弗劳恩霍夫可靠性与微集成研究所 (IZM), 研发工程师、项目经理、嵌入与基板技术团队负责人 Lars Boettcher, Member of the SMTA International Technical Committee, Technical Chair of the IMAPS Device Packaging Conference, Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany - R&D Engineer, Project Manager, Head of the Embedding & Substrate Technologies Team
14:40 - 15:00	车规制造体系对先进封装量产的参照 Reference of automotive manufacturing system to advanced packaging mass production	袁康, 国际 OEM 整车厂, 供应商质量管理 Yuan Kang, International OEM Vehicle Factory, Supplier quality management
15:00 - 15:30	国际圆桌会议 International Roundtable	

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研讨会议程 Conference Program

2026（第二十八届）深圳智能制造及 SMT 技术高级研讨会 2026 (The 28th) Shenzhen IMT&SMT High-level Conference

2026 年 10 月 28 日 9 号馆, NEPCON 剧院, 9H100
28th October 2026 9H100, NEPCON Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:30	电子制造与半导体工厂智能环境监测技术的应用 Application of Intelligent Environmental Monitoring Technology in Electronics Manufacturing and Semiconductor Plants	张红力, 广东屹博智能科技有限公司, 屹博科技市场技术经理 Zhang Hongli, ESAMBER Electronic Science Technology Co., Ltd., Technical Marketing Manager
10:30 - 11:00	清洗赋能 AI 算力、汽车电子新质生产力 Cleaning Empowers New-Quality Productivity in AI Computing Power and Automotive Electronics	王琰, 深圳市合明科技有限公司, 董事长 Wang Lian, Shenzhen Unibright Technology Co., Ltd. Chairman
11:00 - 11:30	电子产品互连可靠性仿真分析技术与应用 Interconnection Reliability Simulation Analysis Technology for Electronic Products and Its Applications	潘浩东, 中国赛宝实验室, 高级工程师、互连可靠性仿真项目主管 Pan Haodong, China CEPREI Laboratory, Senior Engineer, Project Lead of Interconnection Reliability Simulation
11:30 - 12:00	SMT 用焊料的发展及应用现状——精密锡膏 Development and Application Status of SMT Solders — Precision Solder Paste	赵朝辉, 有研纳微新材料(北京)有限公司, 技术总监 Zhao Zhaohui, GRINM NEXUSX ADVANCED MATERIALS (BEIJING) CO., LTD., Technical Director
12:00 - 13:10	午餐时间 / Lunch Break	
13:10 - 13:40	AI 时代电子组装工艺可靠性挑战 Reliability Challenges of Electronics Assembly Processes in the AI Era	聂富刚, 中兴通讯股份有限公司, 研发工艺总工程师 Nie Fugang, ZTE Corporation, Chief R&D Process Engineer
13:40 - 14:10	待定 TBD	康雁, 日联科技集团股份有限公司, 营销专家 Kang Yan, Unicomp Technology Group Co., Ltd., Marketing Specialist
14:10 - 14:40	BGA 空洞, 因何而生, 为何难去除? BGA Voids: Why Do They Form, and Why Are They So Hard to Remove?	贾忠中, 中兴通讯股份有限公司, 高级工程师 Jia Zhongzhong, ZTE Corporation, Senior Engineer
14:40 - 15:10	JT 智能制造解决方案: 智能回流焊设备 Smart Reflow Soldering Systems	王达飞, 劲拓自动化设备股份有限公司, 热流实验室负责人兼视觉产品线负责人 Wang Dafei, Shenzhen JT Automation Equipment Co., Ltd., Thermal Laboratory & Software Development Lead
15:10 - 15:40	电子制造热力学应用及工艺分享 Application of Thermodynamics in Electronics Manufacturing and Process Sharing	李刚, 广东屹博智能科技有限公司, 产品与解决方案总监 Li Gang, Guangdong ESAMBER Intelligent Technology Co., Ltd., Director of Product and Solutions
15:40 - 16:10	待定 TBD	任尧儒, 生意科技 TBD

研讨会议程
Conference Program

通信 & 智能终端高可靠 SMT 高效制程与工艺创新论
Advanced Packaging Enabling Technologies and High-Reliability
Development Forum

2026 年 10 月 27 日 9 号馆, NEPCON 剧院, 9H100
27th October 2026 9H100, NEPCON Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:40 - 10:00	签到 / On-site Registration	
10:00 - 10:10	开场致辞 Opening Remarks	 贺晓荣, 成都市对外科技交流协会会长, 成都市微波射频产业协会执行会长 He Xiaorong, President of Chengdu Association for International Science and Technology Exchange, Executive President of Chengdu Microwave and Radio Frequency Industry Association
10:10 - 10:40	6G 时代 SMT 产业机遇挑战与破局革新之道 Opportunities, Challenges, and Breakthrough & Innovation Strategies for the SMT Industry in the 6G Era	 胡小鹏, 赛迪顾问通信产业研究中心, 总经理 Hu Xiaopeng, CCID Consulting, Communication Industry Research Center, General Manager
10:40 - 11:10	COTS 器件锡须风险端到端管控探索 Exploration of End-to-End Control of Tin Whisker Risks in COTS Components	 潘鹏飞, 魔方卫星科技有限公司, 产保副经理 Pan Pengfei, Magic Cube Satellite Technology Co., Ltd., Deputy Manager, Product Assurance
11:10 - 11:40	板级互连典型失效问题及可靠性保证技术 Typical Failure Problems of Board-Level Interconnects and Reliability Assurance Technologies	 李伟明, 中国赛宝实验室可靠性分析中心, 工艺部副主任 Li Weiming, China CEPREI Laboratory Reliability Analysis Center, Deputy Director, Process Department
11:40 - 13:30	午餐 & 展位参观交流 Lunch Break & Exhibition Visit	
13:30 - 14:00	功率芯片应用中的高温服役风险及对策 High-Temperature Service Risks in Power Chip Applications and Countermeasures	 王世垠, 中兴通讯股份有限公司, 资深工艺专家 Wang Shiyu, ZTE Corporation, Senior Process Expert
14:00 - 14:30	汽车电子 PCBA 多辅料体系催化毒化机理与兼容性协同 Catalytic Poisoning Mechanisms of Multi-Auxiliary-Material Systems in Automotive Electronics PCBA and Compatibility Synergy	 林元, 航盛电子股份有限公司, 电子焊装工艺部部长 Lin Yuan, Shenzhen Hangsheng Electronics Co., Ltd., Electronic Soldering Process Department
14:30 - 15:00	线缆及连接器组件屏蔽效能三同轴测量方法及典型应用 Triaxial Measurement Method and Typical Applications for Shielding Effectiveness of Cable and Connector Assemblies	 邵鄂, 工业和信息化部电子第五研究所, 高级工程师 / 项目总监 Shao E, CEPREI, Senior Engineer / Project Director
15:00 - 15:30	AI 赋能的高功率密度 SMT 制程管控及优化 AI-Empowered Process Control and Optimization for High-Power-Density SMT	 陈志漫, 中车株洲电力机车研究所有限公司, 中车资深工艺专家 Chen Zhiman, CRRC Zhuzhou Institute Co., Ltd., Senior Process Expert [CRRC]
15:30 - 16:00	电子产品热测试技术的演进, 挑战和创新 Evolution, Challenges, and Innovations in Thermal Testing Technology for Electronic Products	 赵振博, 中国赛宝实验室, 高级工程师 Zhao Zhenbo, China CEPREI Laboratory, Senior Engineer
16:00 - 17:30	自由交流 / Open Discussion	

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研讨会议程 Conference Program

2026 年第十届 “快克杯” 全国电子制造行业焊接技能大赛广东分赛区比赛 The 10th “Quick Cup” National Electronics Manufacturing Industry Welding Skills Competition Guangdong Regional Competition

2026 年 10 月 27 日 15 号馆, 竞技场 1, 15A100
27th October 2026 15A100, Arena 1, Hall 15

时间 Time	主题 Topic
08:30 - 09:00	签到 Sign-in
09:00 - 09:30	开幕式 Opening Ceremony
09:30 - 10:40	第一组比赛 Competition (Group 1)
10:50 - 12:00	第二组比赛 Competition (Group 2)
12:00 - 12:40	午餐 Lunch
12:40 - 13:50	第三组比赛 Competition (Group 3)
13:50 - 16:00	联盟标准解读 (评审) Alliance Standard Interpretation (Review)
16:00 - 16:30	颁奖、合影留念 Award Ceremony & Group Photo

研讨会议程
Conference Program

2026 年第三届 “ESAMBER 屹博杯” 全国电子制造行业板级故障分析与维修技能大赛总决赛
The 3rd “ESAMBER Cup” National Electronics Manufacturing Industry Board-Level Fault Analysis and Repair Skills Competition Grand Final

2026 年 10 月 27 日 15 号馆, 竞技场 3, 15F100
27th October 2026 15F100, Arena 3, Hall 15

2026 年 10 月 28-29 日 15 号馆, 竞技场 2, 15C100
28th-29th October 2026 15C100, Arena 2, Hall 15

时间 Time	主题 Topic
2026.10.27	
09:30 - 16:00	《电子装联印制电路板组件 (PCBA) 返工》培训 PCBA Rework Training
2026.10.28	
09:00	到达比赛场地 / Arrival at Venue
09:00 - 09:15	参赛队抽签分组 / Team Sign-in & Group Drawing
09:15 - 09:20	大赛、评委、嘉宾介绍 Introduction of Competition, Judges & Guests
09:20 - 09:30	领导致词及评委颁发证书 Leadership Address & Judge Certificate Presentation
09:30 - 10:00	赛前培训：《短路测试仪应用介绍》 Pre-competition Training: Short Circuit Tester Application
10:00 - 10:30	理论考试 / Theory Examination (All Participants)
10:30 - 12:00	第一组比赛 / Competition (Group 1)
12:00 - 13:00	中餐 / 休息 Lunch & Break
13:00 - 14:30	第二组比赛 / Competition (Group 2)
14:40 - 16:10	第三组比赛 / Competition (Group 3)
2026.10.29	
09:00	到达比赛场馆 / Arrival at Venue
09:00 - 10:30	比赛答辩 / Competition Defense
10:30 - 10:40	休息 / Tea Break
10:40 - 12:00	比赛答辩 / Competition Defense
12:00 - 12:30	颁奖典礼 / Award Ceremony

 刘勇, 广东屹博智能科技有限公司, 技术经理
Liu Yong, Guangdong ESAMBER Intelligent Technology Co., Ltd., Technical Manager

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研讨会日程
Conference Program

2026 年第四届“智汇杯”全国电子制造行业线束线缆制作工艺与操作技能大赛总决赛
The 4th "Zhihui Cup" National Electronics Manufacturing Industry Wire Harness & Cable Fabrication Process and Operation Skills Competition Grand Final

2026 年 10 月 27 日 15 号馆, 竞技场 2, 15C100
27th October 2026 15C100, Arena 2, Hall 15

2026 年 10 月 28-29 日 15 号馆, 竞技场 3, 15F100
28th-29th October 2026 15F100, Arena 3, Hall 15

时间 Time	主题 Topic
2026.10.27	
09:00	到达展会场馆并发放入场证件 Arrival & Badge Collection
09:00 - 09:20	参赛队员签到及分组抽签 Sign-in & Group Drawing
09:20 - 09:40	主持人介绍大赛, 嘉宾及领导致词 Host Opening & Remarks by Guests and Leaders
09:40 - 10:00	评委介绍及证书颁发 Judges Introduction & Certificate Presentation
10:00 - 11:30	第一组 实操比赛 / Group 1 - Practical Competition
11:30 - 12:30	午餐 / 休息 Lunch & Break
12:30 - 14:00	第二组 实操比赛 / Group 2 - Practical Competition
14:10 - 15:40	第三组 实操比赛 / Group 3 - Practical Competition
2026.10.28	
09:30 - 16:00	培训《线束线缆组装技术》 Training: Wire Harness & Cable Assembly Technology
16:00 - 16:30	理论考试 (所有参赛选手参加) Written Exam (All Contestants)
2026.10.29	
09:00 - 11:30	比赛答辩交流 / Competition Defense & Exchange
11:30 - 12:00	颁奖典礼 / Award Ceremony

研讨会议程 Conference Program

2026 第六届“弘快杯”全国电子制造行业 PCB 设计大赛 总决赛 The 6th "Hongkuai Cup" National Electronics Manufacturing Industry PCB Design Competition Grand Final

2026 年 10 月 28-29 日 15 号馆, 竞技场 1, 15A100
28th-29th October 2026 15A100, Arena 1, Hall 15

时间 Time	主题 Topic	演讲嘉宾 Speaker
2026.10.28		
09:00	到达比赛场地 / Arrival at Venue	
09:30 - 09:45	参赛队抽签分组 Team Sign-in & Group Drawing	
09:45 - 09:50	大赛、评委、嘉宾介绍 Introduction of Competition, Judges & Guests	
09:50 - 10:00	领导致词及评委颁发证书 Leadership Address & Judge Certificate Presentation	
10:00 - 11:00	比赛答辩 / Competition Defense	
11:00 - 12:00	技术分享《基于 AI 的电子设计仿真制造平台》 Tech Talk: AI-Based Electronic Design Simulation & Manufacturing Platform	刘雪峰, 上海弘快科技有限公司, 高级行业顾问 Liu Xuefeng, Senior Industry Consultant, Shanghai Hongkuai Technology Co., Ltd.
12:00 - 13:30	中餐 / 休息 Lunch & Break	
13:30 - 15:00	比赛答辩 / Competition Defense	
15:00 - 15:10	休息 / Tea Break	
15:10 - 16:30	比赛答辩 / Competition Defense	
18:30 - 20:30	招待晚宴 (需要提前报名) Gala Dinner (Registration Required)	
2026.10.29		
09:30	到达比赛场馆 / Arrival at Venue	
09:30 - 11:00	比赛答辩 / Competition Defense	
11:00 - 11:30	颁奖典礼 / Award Ceremony	

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研讨会日程 Conference Program

2026 深圳电子工厂节能降碳技术研讨会 2026 Shenzhen Electronics Factory Energy-Saving & Carbon-Reduction Technology Seminar

2026 年 10 月 28 日 9 号馆, 绿色智造剧院, 9D90
28th October 2026 Green Smart Manufacturing Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
13:30 - 14:00	合同能源管理与节能服务产业 Contract Energy Management & the Energy-Saving Service Industry	 孙小亮, 中国节能协会副秘书长, EMCA 常务副主任委员 Sun Xiaoliang, Deputy Secretary-General of China Energy Conservation Association; Standing Vice Chairman of EMCA
14:00 - 14:20	立足电机系统提效, 助力电子工厂低碳发展 Improving Motor System Efficiency to Support Low-Carbon Development of Electronics Factories	 梁栋, 国际铜业协会北京代表处首席代表 Liang Dong, Chief Representative, International Copper Association Beijing Office
14:20 - 14:35	消费电子半导体工厂精准环控低碳冷热的创新与实践 Innovation & Practice of Precision Environmental Control and Low-Carbon Heating/Cooling for Consumer Electronics & Semiconductor Factories	 聂鹏翔, 美的楼宇科技深圳, 直签业务总监 Nie Pengxiang, Direct-Account Business Director, Midea Building Technologies Shenzhen
14:35 - 14:50	以光赋能, Hi-LED 照明解决方案助力企业绿色低碳转型 Empowering Enterprises' Green & Low-Carbon Transition with Light — Hi-LED Lighting Solutions	 庄瞳, 宇碳光启(上海)智能科技有限公司, 总经理 Zhuang Tong, General Manager, Yutang Guangqi (Shanghai) Intelligent Technology Co., Ltd.
14:50 - 15:05	绿色工厂的能源底座: 鑫磊空气动力与冷热能源综合节能实践 The Energy Foundation of a Green Factory: Xinlei Air Power & Integrated Heating/Cooling Energy-Saving Practice	 王晨曦, 鑫磊压缩机股份有限公司, 售前技术专家 Wang Chenxi, Pre-sales Technical Expert, Xinlei Compressor Co., Ltd.
15:05 - 15:20	数字减碳·综合能源服务的电子工厂实践 Digital Carbon Reduction - Practice of Integrated Energy Services in Electronics Factories	 贾攀登, 深圳市富能新能源科技有限公司, 市场总监 Jia Pandeng, Marketing Director, Shenzhen Funeng New Energy Technology Co., Ltd.
15:20 - 15:35	“艾博士”物理 AI 赋能绿色工厂 “Dr. Ai” Physics-Based AI Empowering Green Factories	 逢秀峰, 深圳前海中碳综合能源科技有限公司, 联合创始人、常务副总裁兼 CTO Pang Xiufeng, Co-founder, Executive Vice President & CTO, Shenzhen Qianhai Zhongtan Integrated Energy Technology Co., Ltd.
15:35 - 15:55	电力线载波工厂绿色低碳数字化解决方案 Power Line Carrier (PLC) Green, Low-Carbon & Digitalized Solutions for Factories	 闫瑞顺, 青岛东软载波智能电子有限公司, 产品经理 Yan Ruishun, Product Manager, Qingdao Neusoft Carrier Intelligent Electronics Co., Ltd.

研讨会议程
Conference Program

2026 光通信先进制造技术创新高峰论坛
2026 Advanced Optical Communication Manufacturing Technology
Innovation Summit

2026 年 10 月 27-28 日 13 号馆, 光通信剧院, 13F10
27th-28th October 2026 13F10, Optical Communications Theatre, Hall 13

时间 Time	主题 Topic	演讲嘉宾 Speaker
2026.10.27		
主题: 量产破局·从工艺到产能的落地攻坚 ——聚焦 800G/1.6T 光模块的量产工艺、良率提升与供应链协同 大会主席: 林挺宇, 特聘教授, 深圳职业技术大学集成电路学院		
13:00 - 13:28	嘉宾入场 / 观众签到 Guest / Attendee Registration	
13:28 - 13:30	主持人开场 Opening Remarks by the Host	 林挺宇, 深圳职业技术大学集成电路学院, 特聘教授 Lin Tingyu, Distinguished Professor, School of Integrated Circuits, Shenzhen Polytechnic University
13:30 - 13:40	领导致辞 Keynote Address by the Leaders	 于洪宇, 集成电路学院 院长、教授, 深圳职业技术大学 Yu Hongyu, Professor and Dean of the School of Integrated Circuits, Shenzhen Polytechnic University
13:40 - 14:05	NPO 光引擎技术、产业和应用探讨 NPO Optical Engine: Technology, Industry, and Applications	 吕建新, 首席技术专家, 烽火通信科技股份有限公司 Lv Jianxin, Chief Technical Expert, FiberHome Telecommunication Technologies Co., Ltd.
14:05 - 14:30	CPO 产业化下, 光电异质封装对 Die 分选与固晶设备的新需求 New Demands for Die Sorting and Die Bonding Equipment Driven by CPO Industrialization for Optoelectronic Heterogeneous Packaging	 周谦光, 副总经理, 砺铸智能设备(天津)有限公司 Joseph Zhou Vice President MIT Semiconductor (Tianjin) Company Limited
14:30 - 14:55	3.2T 光模块 AI+ 数字孪生智能制造工厂的建设路径与实践 Construction Path and Practice of the AI + Digital Twin Intelligent Manufacturing Factory for 3.2T Optical Modules	 崔福浩博士, 总经理, 湖北省矢量奇点科技有限公司 Cui Fuhao, General Manager, Hubei Vector Singularity Technology Co., Ltd.
14:55 - 15:20	从失效到良率: EFA 电性失效分析赋能高速光模块量产爬坡 From Failure to Yield: EFA Electrical Failure Analysis Empowers High-Speed Optical Module Mass Production Ramp-Up	 叶昊生, 战略发展总监, 安徽凌光红外科技有限公司 Haosheng Ye Director of Strategic Development Anhui Luxet Infrared Technology Co., Ltd.
15:20 - 15:45	玻璃基板在光通讯的作用 The Application of Glass Substrates in Optical Communication	 倪明明, 应用技术总监, 沃格集团 Ni Mingming, Director of Applied Technology, WG TECH

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研讨会议程 Conference Program

15:45 - 16:25	圆桌论坛：从样品到量产——工艺、设备与材料的协同破局 Roundtable: From Samples to Mass Production - Breaking the Bottlenecks through Synergy of Process, Equipment, and Materials	深圳职业技术大学集成电路学院、沃格集团、安徽凌光红外科技有限公司、烽火通信科技股份有限公司、湖北省矢量奇点科技有限公司 Shenzhen Polytechnic University, WG TECH, Anhui Luxet Infrared Technology Co., Ltd, FiberHome Telecommunication Technologies Co., Ltd, Hubei Vector Singularity Technology Co., Ltd
16:25 - 16:30	合影 Group Photo	全体 ALL
2026.10.28 主题：创新领航·面向未来的下一代制造技术 ——聚焦硅光、CPO、3.2T 及以上速率、AI 智能制造等前沿方向 大会主席：靳永刚，总经理，OIP Technology Singapore		
13:00 - 13:28	嘉宾入场 / 观众签到 Guest/Attendee Registration	
13:28 - 13:30	主持人开场 Opening Remarks by the Host	靳永刚，总经理，OIP Technology Singapore Steve JIN, General Manager, OIP Technology Singapore
13:30 - 13:35	领导致辞 Keynote Address by the Leaders	汪正平教授，中国工程院外籍院士 Professor C.P. Wong, Foreign Member of the Chinese Academy of Engineering
13:35 - 14:00	面向光学共封装 (CPO) 与人工智能 (AI) 的电子与光子封装异构系统集成最新进展 Recent Advances on Heterogeneous System Integration of Electronic and Photonic Packaging for Co-Packaged of Optics (CPO) and Artificial Intelligence (AI)	汪正平教授，中国工程院外籍院士 Professor C.P. Wong, Foreign Member of the Chinese Academy of Engineering
14:00 - 14:20	下一代硅光工艺：标准硅光工艺 +X 的异质集成 Next-Gen SiPh Process: Standard SiPh Process + X Heterogeneous Integration	竺士扬，深圳职业技术大学集成电路学院，特聘教授 Pro. Shiyang Zhu, Distinguished Professor, Shenzhen Polytechnic University
14:20 - 14:40	高速玻璃基 GCP 设计及工程化应用技术 Design and Engineering Application Technology of High-Speed Glass Substrate GCP	魏新启，中兴通讯股份有限公司，资深工艺专家 Wei Xinqi, Senior Process Expert, ZTE Corporation
14:40 - 15:00	板级先进封装赋能光电共封：产业化机遇及技术挑战 Board-Level Advanced Packaging for CPO: Opportunities and Challenges for Industrialization	靳永刚，总经理，OIP Technology Singapore Steve JIN, General Manager, OIP Technology Singapore
15:00 - 15:20	高密度玻璃基 FCBGA 封装基板技术 High-Density Glass-Based FCBGA Substrate Technology	华显刚，广东佛智芯微电子有限公司，总经理 Hua Xiangang, General Manager, Guangdong Fozhixin Microelectronics Technology Co., Ltd.
15:20 - 15:40	先进材料技术推动光收发器向 NPO/CPO 发展 Advanced material technologies to enable the evolution from optical transceivers to NPO and CPO	Garian Lim, 德国德路工业粘合剂，战略业务发展经理 Garian Lim, Strategic Business Development Manager, DELO Industrial Adhesives
15:40 - 16:25	圆桌论坛：创新与量产的平衡——硅光 /CPO 如何从实验室走向规模化 Roundtable: Balancing Innovation and Mass Production - How Silicon Photonics/CPO Transitions from Lab to Scale	深圳职业技术大学集成电路学院、中兴通讯股份有限公司、OIP Technology Singapore、广东佛智芯微电子有限公司、DELO Industrial Adhesives
16:25 - 16:30	合影 Group Photo	全体 ALL

研讨会议程 Conference Program

绿色智能工厂设施大会 Green & Smart Factory Facilities Conference

2026 年 10 月 28 日 9 号馆, 绿色智造剧院, 9D90
28th October 2026 9D90, Green Smart Manufacturing Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:30	签到 / On-site Registration	
10:30 - 10:50	工艺、技术与建筑的整合——高科技芯片厂房建筑设计 Integration of Process, Technology and Architecture — Architectural Design for High-Tech Chip Manufacturing Plants	 晁阳, 中国电子工程设计院股份有限公司, 总建筑师 / 正高级工程师 Chao Yang, China Electronics Engineering Design Institute Co., Ltd., Chief Architect / Professor-level Senior Engineer
10:50 - 11:10	电子制造工厂节能减排管理与实践经验分享 Energy Conservation and Emission Reduction Management and Practical Experience Sharing for Electronic Manufacturing Plants	 杨应龙, 台达电子工业股份有限公司, 研发总监 Yang Yinglong, Delta Electronics, Director of Research and Development
11:10—11:30	零碳园区的实现路径—数智化绿色工厂综合能源服务案例 Implementation Pathways to Zero-Carbon Parks - A Case Study of Integrated Energy Services for Digital-Intelligent Green Factories	 许远超, 中国工业节能与清洁生产协会, 智慧能源与零碳园区分会, 副主任 / 正高级工程师 Xu Yuanchao, China Industrial Energy Conservation and Cleaner Production Association, Smart Energy & Zero-Carbon Industrial Park Branch, Deputy Director, Professorate Senior Engineer
11:30 - 11:50	数据中心测试验证与节能运维 Data Center Testing, Verification and Energy-Efficient O&M	 韩玉仲, 中电投工程研究检测评定中心智慧城市与工程监测所所长, 高级工程师, Han Yuzhong, Senior Engineer, Director of Smart City and Engineering Monitoring Institute, CPI Engineering Research, Testing and Assessment Center
11:50 - 12:10	智慧低碳厂务: 重构 PCB 企业的绿色竞争力 Smart Low-Carbon Business: Rebuilding the Green Competitiveness of PCB Enterprises	 胡珏, 广东迪奥技术有限公司, 技术总工 Hu Jue, Guangdong Di'ao Technology Co., Ltd., Chief Technology Engineer

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研讨会日程
Conference Program

2026 智算生态大会——算力中心基础设施与 AI 应用论坛
2026 Smart Computing Ecosystem Conference - Computing Center
Infrastructure & AI Applications Forum

2026 年 10 月 27 日 13/15 号馆 (二层), 13 号会议室 13-B
27th October 2026 Meeting Room 13-B, Halls 13/15 (Level 2)

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:30 - 10:35	开幕致辞 Opening Remarks	主办方代表 Representative of the Organizer
10:35 - 11:00	面向智算未来，数据中心规划设计趋势与算电协同实践 Towards the Future of Intelligent Computing: Trends in Data Center Planning & Design and Practices in Computing-Power Synergy	杨威，北京电信规划设计院有限公司建筑能源设计院，副院长兼总工程师 Yang Wei, Vice President & Chief Engineer, Architectural Energy Design Institute, Beijing Telecom Planning & Design Institute Co., Ltd.
11:00 - 11:20	运营商 AIDC 算电协同业务发展规划与思考 Development Plan and Considerations for Operators' AIDC Computing-Power Synergy Business	郭云峥，中国移动设计院 中移能源科技(北京)有限公司，能源产品部负责人，资深研究专家 Guo Yunzheng, Head of Energy Product Department, China Mobile Design Institute / China Mobile Energy Technology (Beijing) Co., Ltd.; Senior Research Expert
11:20 - 11:40	百兆瓦级(十万卡) AIDC 基础设施实践分享 Practical Insights on Hundred-Megawatt-Class (100,000-GPU) AIDC Infrastructure	张鹏博士，中科曙光副总裁，曙光数据基础设施创新技术(北京)股份有限公司，副总裁 Dr. Zhang Peng, Vice President, Dawning Data Infrastructure Innovation Technology (Beijing) Co., Ltd.; Senior Vice President, Sugon
11:40 - 12:00	智算未来：AI 计算技术发展趋势及方案 Practical Insights on Hundred-Megawatt-Class (100,000-GPU) AIDC Infrastructure	李朕，浪潮计算机科技有限公司，能源交通行业部，首席架构师 Li Zhen, Chief Architect, Energy & Transportation Industry Division, Inspur Computer Technology Co., Ltd.
12:00 - 13:30	午休，参观展会 / Lunch Break & Exhibition Visit	
13:30 - 13:50	Rubin 800V 系统落地方案分享 Rubin 800V System Implementation Solution Sharing	赵呈涛，维谛，总监 Zhao Chengtao, Vertiv, Director
13:50 - 14:10	面向 AIDC 高密度算力：CFD 仿真在冷却系统中的创新应用 For AIDC High-Density Computing: Innovative Applications of CFD Simulation in Cooling Systems	黄冬梅博士，北京瑞思博创科技有限公司，数字孪生专家 Dr. Huang Dongmei, Digital Twin Expert, Beijing Ruisibo Chuang Technology Co., Ltd.
14:10 - 14:30	泵阀协同，阀控能效 - 热管理核心部件重塑 AI 算力液冷系统能效边界 Pump-Valve Synergy: Valve-Controlled Energy Efficiency - Core Thermal Management Components Reshaping the Energy Efficiency Boundaries of AI Computing Liquid Cooling Systems	魏琪，美芝 & 威灵数储行业，应用推广专家(美的) Wei Qi, M&C / Welling Data Industry, Application Promotion Expert (Midea)
14:30 - 14:50	新一代数字基础设施，绿色液冷一体化方案 Next-Generation Digital Infrastructure - Green Liquid-Cooling Integrated Solutions	朱维强，天津提尔科技有限公司，市场总监 Zhu Weiqiang, Tianjin Tier Technology Co., Ltd., Marketing Director

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研讨会议程 Conference Program

14:50 - 15:10	探索算电协同，构筑数据中心高质量发展之路 Focused Research on Data Center Immersion Cooling Systems to Empower Green Computing	杨晓平，北京电子学会计算机委员会专家委员，《数智元》杂志专家组专家 Yang Xiaoping, Expert Member, Computer Committee, Beijing Institute of Electronics; Expert, Expert Panel of "Digital Intelligence" Magazine
15:10 - 15:30	华南地区 AIDC 高密算力定制化项目实践分享 Practical Insights on Customized AIDC High-Density Computing Projects in South China	刘圣庆，中国联通广东分公司网络运营事业部基础设施维护经理，专家 Liu Shengqing, Infrastructure Maintenance Manager & Expert, Network Operations Division, China Unicom Guangdong Branch
15:30 - 15:50	智变·共生 加速 AI 基础设施持续升级 Intelligent Transformation · Symbiosis - Accelerating the Continuous Upgrade of AI Infrastructure	刘远洋，商汤科技运营商业事业部，总监 Liu Yuanyang, SenseTime, Director of Carrier Business Unit
15:50 - 16:10	算力全生命周期服务 AIDC full lifecycle Services	林迎全，北京亚康万玮信息技术股份有限公司，副总裁 VP 兼战略发展部总经理 Lin Yingquan, Beijing Asiacom Information Technology Co., Ltd., Strategic Development Department GM
16:10 - 16:30	AI 时代高速光互联技术演进与产业实践 Evolution of High-Speed Optical Interconnect Technology and Industrial Practice in the AI Era	吕建新，烽火通信科技股份有限公司，首席技术专家 Lv Jianxin, FiberHome Telecommunication Technologies Co., Ltd., Chief Technology Expert

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研讨会日程 Conference Program

2026 智算生态大会——AI 算力场景应用与产业融合·智算中心与工业场景应用论坛

2026 Smart Computing Ecosystem Conference - Intelligent Computing Center & Industrial Scenarios Forum

2026 年 10 月 28 日 15 号馆, 1 号会议室
28th October 2026 Conference Room 1, Hall 15

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:30	嘉宾及专业观众签到 / Guest & Professional Visitor Registration	
10:30 - 10:40	领导致辞 Leadership Address	深圳市龙华区投资促进服务中心 Investment Promotion Service Center of Longhua District, Shenzhen
10:40 - 11:00	工业智算及 Token 发展趋势研究 Research on Industrial Intelligent Computing and Token Development Trends	中国工业互联网研究院 China Academy of Industrial Internet
11:00 - 11:20	算力入网, 智造入景——AI 算力产业从基础设施到场景智能的需求迁移 Computing Power Entering the Network, Intelligent Manufacturing Entering Scenarios: Demand Shift in the AI Computing Industry from Infrastructure to Scenario Intelligence	李强, 海光信息技术股份有限公司, 解决方案专家 Li Qiang, Solution Expert, Hygon Information Technology Co., Ltd.
11:20 - 11:40	玻璃基板与板级封装: 新时代高性能芯片封装互连的关键 Glass Substrates and Panel-Level Packaging: The Key to High-Performance Chip Packaging Interconnection in the New Era	于大全, 厦门云天半导体科技有限公司, CEO Yu Daquan, Xiamen Yuntian Semiconductor Technology Co., Ltd., CEO
11:40 - 12:00	液冷基础设施在 AIDC 发展中的应用与实践 Applications and Practices of Liquid Cooling Infrastructure in AIDC Development	胡亚伟, 曙光数据基础设施创新技术(北京)股份有限公司, 华南区总监 Hu Yawei, South China Regional Director, Dawning Data Infrastructure Innovation Technology (Beijing) Co., Ltd.
12:00 - 13:40	午休, 参观展会 Lunch Break & Exhibition Visit	
13:40 - 14:00	中国液冷全预制化撬块数据中心 China Liquid-Cooling Fully Prefabricated Modular Data Center	许伟忠, 深圳市得益节能科技股份有限公司, 董事长 Xu Weizhong, Chairman, Shenzhen Deyi Energy-saving Technology Co., Ltd.
14:00 - 14:20	AI 在电子产线 AOI 检测算法的运用 Application of AI in AOI Inspection Algorithms on Electronic Production Lines	李志求, 信维通信集团, 高级工艺经理 Li Zhiqiu, Senior Process Manager, Sunway Communication Group
14:20 - 14:40	从地面云平台到星上智能: 航天 AI 的软件架构与算力协同实践 From Ground Cloud Platforms to On-Board Intelligence: Software Architecture and Computing Power Collaboration Practices for Aerospace AI	唐卫涛, 西安中科天塔科技股份有限公司, 解决方案部部长 / 高级工程师 Tang Weitao, Xi'an Zhongke Tianta Technology Co., Ltd., Solutions Department Director / Senior Engineer
14:40 - 15:00	AI+ 工业互联网助力制造业数智化升级 On-Board Intelligence, Aerospace Computing, and High-Reliability Electronics Requirements	徐海涛, 卡奥斯物联科技股份有限公司, 企业级工业互联网平台解决方案总监 Xu Haitao, Director of Enterprise-Level Industrial Internet Platform Solutions, COSMOPlat

研讨会议程 Conference Program

15:00 - 15:20	让算力创造业务价值：数字员工与 Token 全周期治理 Making Computing Power Create Business Value: Digital Employees and Full-Cycle Token Governance	 张晓华 · 授客 AI, CEO Zhang Xiaohua, CEO, Zevolve.AI
15:20 - 15:40	AI 在先进制造业的最佳实践——研造双轮共生 Best Practices of AI in Advanced Manufacturing - Symbiosis of R&D and Manufacturing	 郭亮, 上海东岚创智科技有限公司, 创始人 Guo Liang, Founder, Shanghai Donglan Chuangzhi Technology Co., Ltd.
15:40 - 16:00	圆桌讨论：从芯片到生态系统：场景需求如何重构算力与电子供应链 Panel Discussion: From Chips to Ecosystems - How Scenario Requirements Are Reshaping Computing Power and Electronics Supply Chains	 张晓磊, 长光卫星技术股份有限公司, 经营发展部部长 Zhang Xiaolei, Chang Guang Satellite, Director of Business Development Department 黄华镜, 深圳市英维克科技股份有限公司, IDC 产品总经理 Huang Huajing, Envicool Technology, General Manager of IDC Products 汤尔昌, 齐力半导体(绍兴)有限公司, TPM 总监 Tang Erchang, Qili Semiconductor (Shaoxing) Co., Ltd., TPM Director, 王润泽, 光羽芯辰科技有限公司, 华南区产品市场总监 Wang Runze, Guangyu Xincheng Technology Co., Ltd., Product Marketing Director, South China Region

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研讨会日程
Conference Program

2026 AI 算力产业生态合作创新（深圳）大会
2026 AI Computing Power Industry Ecosystem Cooperation & Innovation (Shenzhen) Conference

2026 年 10 月 29 日 13 号馆，光通信剧院，13F10
29th October 2026 13F10, Optical Communications Theatre, Hall 13

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:30	东数西算战略下全国算力网络建设与产业机遇 National Computing Network Development and Industrial Opportunities under the East-to-West Computing Strategy	高庆浩，中国信息通信研究院华东分院，副主任 Gao Qinghao, Department of Digitalization and Emerging Technologies, CAICT East Branch, Deputy Director
10:30 - 10:50	数智创新—重构生产级 A 全栈基础设施 Digital Intelligent Innovation - Re architecting Production Grade Full Stack AI Infrastructure	林庆龙，深信服科技股份有限公司，副总裁 Qinglong Lin, Sangfor Technologies Inc., Vice President
10:50 - 11:10	以全国产 AI 芯片为基，锻造高质量 Token 算力底座 Forging a High-Quality Token Compute Base on a Fully Domestic AI Chip Supply Chain	刘江贤，深圳江原科技有限公司，联合创始人 Liu Jiangxian, Shenzhen Eurigin Technology Co., Ltd., Co-founder and Chief Strategy Officer
11:10 - 11:30	从异构算力调度到 Token 工厂实践分享 Practical Sharing from Heterogeneous Computing Power Scheduling to Token Factory	王计登，贵州数据宝网络科技有限公司，首席 AI 算力科学家 Jordan Wang, BigData-Bao Network Technology Co., Ltd., Guizhou, Chief AI Computing Power Scientist
11:30 - 11:50	绿色低碳算力：液冷技术与算力节能降耗实践 Air-Liquid Hybrid Cooling: Exploring Energy-Efficient Cooling Technology Pathways for Data Centers	柯耿，维谛技术有限公司，产品部营销经理 Ke Geng, Vertiv, Marketing Manager in the Product Division
11:50 - 12:10	圆桌讨论：AI 算力产业生态合作与区域落地 Roundtable Discussion: AI Computing Power Industry Ecosystem Collaboration and Regional Implementation	高庆浩，林庆龙，刘江贤，王计登，柯耿 Gao Qinghao, Lin Qinglong, Liu Jiangxian, Jordan Wang, Ke Geng 肖鹏，天融信科技集团股份有限公司深圳平台，副总经理 Xiao Peng, Shenzhen Platform, Topsec Technologies Group Co., Ltd., Deputy General Manager

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研讨会议程
Conference Program

车规电子智能制造与精密工艺创新研讨会
Forum on Intelligent Manufacturing and Precision Process
Innovation for Automotive-grade Electronics

2026 年 10 月 27 日 13 号馆, 13G30, AWC 剧院
27th October 2026 13G30, AWC Theater, Hall 13

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:30 - 10:40	致欢迎辞 Welcome Remarks	 主持人：孙城，造车网主编 Host: Sun Cheng, Editor-in-Chief, Zaoche
10:40 - 11:00	康耐视 2D/3D 视觉系统：让 AI 触手可及 Cognex 2D/3D Vision Systems: Making AI Within Reach	 李江博，康耐视视觉检测系统（上海）有限公司，华南大区 3D 产品销售经理 Li Jiangbo, 3D Products - South China Regional Sales Manager, Cognex Corporation
11:00 - 11:20	从整车到零部件：和利时汽车智造全链解决方案 From Complete Vehicles to Components: Hollysys Full-Chain Intelligent Manufacturing Solutions for the Automotive Industry	 王辉，北京和利时系统工程有限公司，汽车事业部总经理 Wang Hui, General Manager of Automotive Division, Beijing HollySys System Engineering Co., Ltd.
11:20 - 11:40	车规电子可靠性测试标准（AEC-Q）与失效分析溯源 AEC-Q Reliability Test Standards for Automotive Electronics and Failure Analysis Traceability	 TÜV 莱茵 TÜV Rheinland
11:40 - 12:00	车用电子智能制造质量自动管控与溯源体系建设 Building Automated Quality Control and Traceability Systems for Smart Manufacturing of Automotive Electronics	 庄立新，杭州海康机器人股份有限公司，深圳分公司大客户销售总监 Zhuang Lixin, Key Account Sales Director, Shenzhen Branch, Hangzhou Hikrobot Co., Ltd.
12:00 - 13:30	午餐 / 观展 Lunch Break & Exhibition Visit	
13:30 - 13:50	通用智能机器人赋能全球新质生产力——JAKA 技术创新与产业应用实践分享 General-Purpose Intelligent Robots Driving the World's New Quality Productive Forces - JAKA's Technological Innovation and Industry Applications	 周鹏程，上海节卡机器人科技有限公司，汽车事业部高级销售经理 Zhou Pengcheng, Senior Sales Manager of Automotive Division, Shanghai JAKA Robotics Ltd
13:50 - 14:10	深耕汽车智造 共塑具身生态 - 珞石机器人赋能汽车产业柔性升级 Deep Dive into Automotive Intelligent Manufacturing, Co-Shaping the Embodied AI Ecosystem - ROKAE Robots Enabling Flexible Transformation of Automotive Production	 胡海峰，珞石机器人，客户高级总监 Hu Haifeng, Senior Key Account Director, ROKAE ROBOTICS
14:10 - 14:30	驾驭车规电子应用潮湿鲁棒性 - 失效机理及预防 Tackling Humidity Robustness for Automotive Electronics - Understanding Failure Mechanisms and Prevention Strategies	 王克同，洁创贸易（上海）有限公司，北亚区 R&S 部门经理 Wang Ketong, Manager of R&S Department - North Asia Region, Zestron Trading (Shanghai) Co., Ltd.
14:30 - 14:50	以材料创新推动车载显示高质量发展 Driving High-Quality Development of Automotive Displays through Materials Innovation	 吴位君，东莞市派乐玛新材料技术开发有限公司，应用技术专家 Wu Weijun, Application Technology Expert, Dongguan Polomo New Materials Technology Development Co., Ltd.
14:50 - 15:10	AI 多模态视觉，守护汽车电子精密品质 AI-Powered Multimodal Vision: Safeguarding Precision Quality in Automotive Electronics	 刘波文，梅卡曼德（雄安）机器人科技股份有限公司，销售经理 Liu Bowen, Sales Manager, Mech-Mind Robotics Technologies Ltd.

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研讨会日程
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15:10 - 15:30	ESD，车载电子可靠性的基础保障 ESD: The Foundation of Automotive Electronics Reliability	李雪晴，深圳市白光电子科技有限公司，技术部经理 Li Xueqing, Manager, Technical Department, Shenzhen Bakon Electronic Technology Co., Ltd.
15:30 - 15:50	结束语 Conclusion	主持人：孙城，造车网主编 Host: Sun Cheng, Editor-in-Chief, Zaoche

智能汽车“百家论坛”第三十期
AWC 破卷突围—AI 驱动汽车升级的产业需求与机遇
Intelligent Vehicle Forum: Industrial Demands and Opportunities in AI-Driven Automotive Upgrades

2026 年 10 月 28 日 13 号馆, 13G30, AWC 剧院
28th October 2026 13G30, AWC Theater, Hall 13

时间 Time	主题 Topic	演讲嘉宾 Speaker
13:30 - 14:00	签到 / Check-in	
14:00 - 14:10	主持人开场 / Opening by the Host	
14:10 - 14:30	墨鸾 AI OS 驱动新一代整车智能化架构升级 Moyuan AI OS: Driving the Upgrade of Next-Generation Vehicle Intelligent Architecture	廖纬德，航盛电子技术中心创新规划院高级专家 Liao Weide, Senior Expert, Innovation Planning Institute, Technology Center, Shenzhen Hangsheng Electronics Co., Ltd.
14:30 - 14:50	HAI 重新定义智能座舱的 AI 原生场景 HAI Redefining AI-Native Scenarios for Intelligent Cockpits	张天龙，大众汽车集团中国 AI 座舱产品负责人 Zhang Tianlong, Head of China AI Cockpit Products, Volkswagen Group
14:50 - 15:10	AI+SAP 双引擎：汽车智能制造全球布局与创新运营 AI + SAP Dual Engine: Global Layout and Innovative Operation of Intelligent Manufacturing in the Automotive Industry	王建良，迪森科技执行总裁 Wang Jianliang, Chief Executive Officer, Decision Technology
15:10 - 15:30	AI 全链路赋能，重塑汽车产业全新竞争格局 Full-Chain AI Empowerment: Reshaping the Competitive Landscape of the Automotive Industry	曾繁磊，华为技术有限公司汽车行业数智化解决方案首席架构师 Zeng Fanlei, Chief Architect of Digital & Intelligent Solutions for Automotive Industry, Huawei Technologies Co., Ltd.
15:30 - 15:50	从“+AI”到“AI+”汽车电子行业组织效能重塑实践 From "+AI" to "AI+": Reshaping Organizational Effectiveness in the Automotive Electronics Industry	贝加，浙江实在智能科技有限公司 AI 企业解决方案专家 Bei Jia, AI Enterprise Solutions Specialist, Zhejiang Intelligence Indeed Technology Co., Ltd.
15:50 - 16:10	驶向全球的必修课—汽车产业知识产权风险与 FTO 实战 Navigating the Global Road: Automotive IP Risk Management and FTO in Practice	吴立，前比亚迪股份有限公司知识产权经理、众鼎知识产权集团副总经理 Wu Li, Deputy General Manager, Zhongding Intellectual Property Group Co., Ltd., Ex-IP Manager, BYD Auto Industry CO., LTD.
16:10 - 16:30	透视城市竞争力，洞见产业新机遇—中国城市智能网联新能源汽车产业集群竞争力指数报告 (2026) Insight into Urban Competitiveness, Vision for Industrial Opportunities: 2026 China ICV Industry Cluster Competitiveness Index Report	张峻旗，深圳国家高技术产业创新中心研究员 Zhang Junqi, Research Fellow, Shenzhen National High-tech Industry Innovation Center
16:30 - 16:40	产业总结 & 共识发布 Industry Summary & Consensus Release	

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研讨会议程 Conference Program

2026 工业部件赋能智能装备创新大会 2026 Industrial Components Empowering Intelligent Equipment Innovation Conference

2026 年 10 月 27 日 9 号馆, 绿色智造剧院, 9D90
27th October 2026 9D90, Green Smart Manufacturing Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30 - 10:00	嘉宾入场 / 观众签到 Guest / Attendee Registration	
10:00 - 10:05	主持人开场 Opening Remarks by the Host	
10:05 - 10:35	工控主板在智能装备中的应用 Application of Industrial Control Motherboards in Intelligent Equipment	 信步科技 Seavo Technology
10:35 - 11:05	全国产运动控制实时内核, 助力电子和半导体装备产业升级 Fully Domestic Real-Time Motion Control Kernel Facilitating the Upgrade of Electronic and Semiconductor Equipment Industry	 胡明权, 深圳市正运动技术有限公司, 总助 Hu MingQuan, Zmotion, Executive Assistant
11:05 - 11:35	运控+AOI 低代码编程, 让点胶 / 涂覆 / 焊锡 / 螺丝设备商拥有自研的软件 Low-code programming for motion control & AOI. Empower dispensing, coating, soldering and screw machine builders to own self-developed software	 王冲, 深圳百谷智能工业有限公司, 副总经理兼技术总监 Wang Chong, Shenzhen Baigu Intelligent Industry Co., Ltd., Deputy General Manager & CTO
11:35 - 12:05	Lunch Break / 午餐	

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研讨会议程 Conference Program

2026 智慧工厂与 AI 自动化深度融合论坛 2026 Smart Factory & AI Automation Integration Forum

2026 年 10 月 27 日 9 号馆, 绿色智造剧院, 9D90
27th October 2026 9D90, Green Smart Manufacturing Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
13:30 - 14:00	嘉宾入场 / 观众签到 Guest/Attendee Registration	
14:00 - 14:30	工业智能体赋能智能工厂：从数据响应到自主决策 Industrial AI Agents Empowering Smart Factories: From Data Response to Autonomous Decision-Making	 李超, 深圳市工业 4.0 促进会, 秘书长 Li Chao, Secretary-General, Shenzhen Industrial 4.0 Promotion Association
14:30 - 15:00	人机协同机器人在柔性装配线的规模化部署实践 Large-Scale Deployment of Human-Robot Collaborative Systems in Flexible Assembly Lines	 何朋兵, 艾利特智能机器人股份有限公司, 华南分公司总经理 He Pengbing, Elite Intelligent Robot Co., Ltd., General Manager, South China Branch
15:00 - 15:30	仿人化机器人技术重塑电子行业柔性制造新边界 Humanoid Robot Technology Reshaping the New Boundaries of Flexible Manufacturing in the Electronics Industry	 刘宇, 非夕机器人, 电子电气行业高级商务拓展经理 Liu Yu, Flexiv Robotics, Senior Business Development Manager, Electronics & Electrical Industry
15:30 - 15:45	从 SMT 产线到仓储物流的 AI 集成路径 AI Integration Path from SMT Production Lines to Warehousing and Logistics	 盐城市工业和信息化局 Yancheng Bureau of Industry and Information Technology
15:45 - 16:15	落地马来西亚：设厂之路与投资新机遇 The Journey and New Opportunities of Setting Up a Factory	 邓维豪, 绿盛世, 销售部经理 AARON TENG WAI HOU, ECO WORLD DEVELOPMENT GROUP BHD, MANAGER, SALES AND MARKETING
16:15 - 16:45	商务交流 / Business Networking	

研讨会议程 Conference Program

2026 智能仓储及智慧物流技术峰会 2026 Intelligent Warehousing & Smart Logistics Technology Summit

2026 年 10 月 29 日 9 号馆, 绿色智造剧院, 9D90
29th October 2026 9D90, Green Smart Manufacturing Theatre, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:30	嘉宾入场 / 观众签到 Guest/Attendee Registration	
10:30 - 10:55	智能物流变革助力制造企业高质量发展 Intelligent Logistics Transformation Empowering High-Quality Development of Manufacturing Enterprises	 董永旺, 安得智联供应链科技股份有限公司, 智能物流部部长 Dong Yongwang, Annto Supply Chain Technology Co., Ltd., Director of Intelligent Logistics Department
10:55 - 11:25	柔性仓储新范式: 海柔创新 ACR 如何重塑智能工厂物流 New Paradigm of Flexible Warehousing: How Hai Robotics ACR Reshapes Smart Factory Logistics	 周丽华, 深圳市海柔创新科技有限公司, 海柔创新大中华地区业务拓展负责人 Zhou lihua, Head of Business Development, Greater China, HAI ROBOTICS Co., Ltd.
11:25 - 11:55	将投资转化为价值驱动: 电子智造的仓库焕新计划 From cost center to value driver - Revitalizing Warehouses in Electronics Smart Factories	 金香花, 卡迪斯物流设备(北京)有限公司上海分公司, 销售经理 Alicia Jin, Kardex Logistic System (Beijing) Co., Ltd. Shanghai Branch, Sales Manager
11:55 - 12:25	京东物流科技智能仓储行业探索与挑战 JD Logistics Technology's Exploration and Challenges in the Intelligent Warehousing Industry	 张振林, 京东物流科技, 方案总监 Lyn, JD Logistics Technology, Solution Director

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研讨会会议程
Conference Program

2026 具身智能技术创新与供应链协同论坛
2026 Embodied Intelligence Technology Innovation and Supply Chain Synergy Forum

2026 年 10 月 27 日 7 号馆, 7F90, 具身智能剧院 1
27th October 2026 7F90, Embodied Intelligence Theatre 1, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30 - 10:00	嘉宾入场 / 观众签到 Guest/Attendee Registration	
10:00 - 10:35	大模型重新定义机器人 How does AI redefine robot?	 周奕豪, 博士, 华南理工大学自动化科学与工程学院 Dr. Bernard, SCUT
10:35 - 11:05	从“看得懂”到“安全作业”: 面向电力与智算中心运维的工业具身智能平台 From Perception to Safe Action: An Industrial Embodied AI Platform for Power Systems and AI Data Centres	 秦征, 杭州申昊科技股份有限公司, 具身通用机器人研发部首席技术官 Zheng Qin, Hangzhou Shenhao Technology Co., Ltd., Chief Technology Officer, Embodied General Robotics R&D Department
11:05 - 11:35	从场景原生到进化协同: 让机器人大脑在高价值场景敢上场 From Scenario-Native to Evolutionary Synergy: Enabling Robotic Brains in High-Value Scenarios	 孙腾, 深圳若愚科技有限公司, 创始人兼 CEO Teng Sun, Shenzhen Ruoyu Technology Co., Ltd., Founder & CEO
11:35 - 12:05	NSK 在人形机器人行业中产品开发及新技术应用 NSK Product Development and Application of New Technologies in the Humanoid Robot Industry	 王洪亮, 恩斯克(中国)研究开发有限公司, 技术中心所长 Hongliang Wang, NSK [China] Research and Development Co., Ltd., Tech General Manager
12:05 - 13:30	午餐 / Lunch	
13:30 - 14:00	具身机器人产业发展现状与趋势 Current Status and Trends of the Embodied Robot Industry	 李进科, 人形机器人场景应用联盟, 秘书长 Jinke Li, Humanoid Robot Scene Application Alliance, Executive Secretary
14:00 - 14:30	具身智能的视觉感知与应用 Visual Perception for Embodied AI	 史东平, 联合影像, 产品总监 Dongping Shi, Union Image, Product Director
14:30 - 15:00	智能家居服务机器人场景化测评思考 Reflections on Scenario-Based Evaluation of Smart Home Service Robots	 李岳洪, 威凯检测技术有限公司, 机器人事业部总工程师 Yuehong Li, CVC Testing Technology Co., Ltd., Robotics Division, Chief Engineer
15:00 - 15:30	从频繁更换到持久可靠: 长寿命自超滑空心杯电机赋能灵巧手关节模组 From Frequent Replacement to Lasting Reliability: Self-SuperLubricity Coreless Motors Powering Dexterous Hand Joint Modules	 聂锦辉, 深圳清力技术有限公司, 电机部长 Jinhui Nie, Friction X, Motor department Head
15:30 - 16:00	具身智能出海: 跨境交易风险识别与合规管理 Embodied Intelligence Going Global: Cross-Border Transaction Risk and Compliance Management	 童颖, 律商联讯风险信息, 大中华区战略负责人 Ying Tong, LexisNexis Risk Solutions, Greater China, Head of Strategy
16:00 - 16:30	商务交流 / Networking	

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研讨会议程 Conference Program

2026 具身机器人工业智造升级论坛 2026 Embodied Robotics Forum for Smart Manufacturing Industrial Upgrade

2026 年 10 月 27 日 7 号馆, 7A90, 具身智能剧院 2
27th October 2026 7A90, Embodied Intelligence Theatre 2, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30 - 10:00	签到 & 自由交流 Registration & Networking	
10:00 - 10:05	主持人开场 Opening Remarks by the Host	
10:05 - 10:30	《告别“盆景”时代:以“快”制胜的具身智能规模化落地新范式》 Farewell to the "Bonsai" Era: A New Paradigm for Scalable Deployment of Embodied Intelligence Winning through Speed	 北京阿米奥机器人科技有限公司 Beijing Amigos Robotics Technology Co., Ltd.
10:30 - 11:00	科技创新赋能产业, 专业物流服务展会 Technology Innovation Empowers Industry, Professional Logistics for Exhibitions	 杨术林, 顺丰集团, 展会总经理 Shulin Yang, SF Group, General Manager of Exhibition
11:00 - 11:30	高效转运柔性上料精密拧紧——壕翎智能机器人汽车产线实战赋能新一代智能制造 Efficient Transfer, Flexible Feeding & Precision Tightening - Haoling Intelligent Robots Empower New-Generation Intelligent Manufacturing with Practical Deployment on Automotive Production Lines	 黎炯, 深圳壕翎机器人有限公司, 总经理 Jiong Li, Shenzhen Haoling Robot Co., Ltd., CEO
11:30 - 12:00	人形机器人码垛搬运规模化落地路径 Pathways for Large-Scale Deployment of Humanoid Robots in Palletizing & Handling	 优必选 UBTech

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研讨会日程 Conference Program

2026 具身机器人商用服务落地论坛 2026 Embodied Robotics Forum for Commercial Service Deployment

2026 年 10 月 27 日 7 号馆, 7A90, 具身智能剧院 2
27th October 2026 7A90, Embodied Intelligence Theatre 2, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
13:00 - 13:30	签到 & 自由交流 / Registration & Networking	
13:30	主持人开场 / Opening Remarks by the Host	
13:30 - 14:00	具身智能时代 越秀场景之约 The Era of Embodied Intelligence: Yuexiu's Covenant of Scenarios	张琪, 广州市越秀区人工智能产业协会, 副秘书长 Qi Zhang, Yuexiu District Artificial Intelligence Industry Association, Deputy Secretary-General
14:00 - 14:20	《为真实世界培养智能: 人形机器人在 AI 通识教育中的价值与实践》 Cultivating Intelligence for the Real World: Value and Practice of Humanoid Robots in AI General Education	黄茜, 北京加速进化科技有限公司, 中国销售副总裁 Betty, Booster Robotics, VP of China Sales
14:20 - 14:40	仿真美女机器人的应用场景及发展前景 Application Scenarios and Development Prospects of Humanoid Beauty Robots	李建博, 深圳大象安泰科技有限公司, 商务总监 Jianbo Li, Shenzhen Elephant Antai Technology Co., Ltd., Business Director
14:40 - 15:00	如何重构文旅场景的差异化爆款? 机器人演艺服务常态化破局探索 How Can Tourism Destinations Create Differentiated Hit Experiences? Exploring the Path to Sustainable Robot Entertainment Services Applications	李可为, 擎天租(上海)科技有限公司, 首席营销官 Kewei Li, SHAREBOT, Chief Marketing Officer (CMO)

2026 具身机器人特种极限作业论坛 2026 Embodied Robotics Forum for Special Purpose Extreme Environment Operations

2026 年 10 月 27 日 7 号馆, 7A90, 具身智能剧院 2
27th October 2026 7A90, Embodied Intelligence Theatre 2, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
15:00 - 15:20	特种机器人赋能全球危化企业高质量发展 Specialty robots empower high-quality development of global hazardous materials enterprises	孙喆, 七腾机器人, 全球战略中心副总裁 April Sun, Sevnce Robotics Co., Ltd., Global Strategy Center VP
15:20 - 15:40	让机器人走进高危现场: 端侧具身智能技术与实践 Empowering Robots for the Real World: Edge Embodied AI in High-Risk Industrial Applications	周奇民, 耀行科技(北京)有限公司, 创始人 Qimin Zhou, YORIX Technology (Beijing) Co., Ltd., Founder
15:40 - 16:00	高危场景安全生产无人化改造实战经验与风险管控 Practical Experience in Unmanned Transformation of Production Safety in High-Risk Scenarios and Risk Control	暂定 To Be Confirmed
16:00 - 16:20	特种场景定制化二次开发与系统适配落地实践 Deployment Practices of Customized Secondary Development and System Adaptation for Special-Purpose Scenarios	暂定 To Be Confirmed

研讨会议程 Conference Program

2026 具身智能产业趋势与产品能力升级论坛 2026 Embodied Intelligence Forum for Industry Trends & Product Performance Upgrade

2026 年 10 月 28 日 7 号馆, 7F90, 具身智能剧院 1
28th October 2026 7F90, Embodied Intelligence Theatre 1, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30 - 10:00	签到 & 自由交流 / Registration & Networking	
10:00 - 10:05	主持人开场 / Opening Remarks by the Host	
10:05 - 10:35	从单品开发到全品类布局——机器人系统集成的规模化复制之路 From Single-Product Development to Full-Category Layout: The Path to Scalable Replication in Robot System Integration	 刘永洪, 浙江华巡智能科技有限公司, 总经理 Yonghong Liu, Zhejiang Huaxun Intelligent Technology Co., Ltd., General Manager
10:35 - 11:05	机器人如何真正进工厂——工业场景的二次开发与集成落地 How Robots Truly Enter Factories: Secondary Development and Integration Deployment in Industrial Scenarios	 苏州晶动之星智能科技有限公司 Energon Intelligent Technology Co., Ltd.
11:05 - 11:35	AI 机器人技术重构线下娱乐消费新场景 AI Robot Technology Reshaping New Offline Entertainment Consumption Scenarios	 朱永强, 乐博空间(北京)科技服务有限责任公司, 创始人兼 CEO Alex Zhu, Robo Space, Founder & CEO
11:35 - 12:05	机器人运动数据的未来 The Future Of Robotic Motion Data	 陈奕延, 灵科, CEO 兼创始人 LINEARK, CEO & Co-Founder, Dr. Ian Tan Wei Lum
12:05 - 13:30	午餐 & 观展 / Lunch & Exhibition Visit	
13:30 - 14:00	签到 / Registration	
14:00 - 14:25	无线缆缠绕的人型机器人: 延长机器人寿命, 充电并同步实现千兆数据回传 Cable-Tangle-Free Humanoid Robots: Extend Robot Service Life, Enable Charging and Gigabit Data Backhaul Simultaneously	 金永东, UNIQCONN INC. (韩国) CEO Kim Young Dong, UNIQCONN INC. (South Korea), CEO
14:25 - 14:50	仿真自动化赋能机器人轻量化与可靠性设计 Simulation Automation Empowers Robot Lightweighting & Reliability Design	 李冬生, 深圳市有限元科技有限公司, 技术总监 Tommy Li, Shenzhen Finite Element Technology Co., Ltd., Technical Director
14:50 - 15:15	更好的激光雷达助力具身智能更快的规模化 Better LiDAR Accelerates the Scaling of Embodied AI	 罗杰, 图达通智能科技(苏州)有限公司, RoboX 事业部负责人 Roger Luo, Seyond, Head of RoboX business unit
15:15 - 15:40	面向具身智能的下一代视觉感知: 从事件相机到感算一体 Next-Generation Visual Perception for Embodied Intelligence: From Event Cameras to Sensing-Computing Integration	 刘敏, 动微视觉(北京)科技有限公司, CEO Liu Ming, DVSense LTD, CEO
15:40 - 16:05	商业破局: 2026 具身机器人量产元年下的运营与市场模式创新 Business Breakthrough: Operations and Go-to-Market Model Innovation in the 2026 Mass-Production Year of Embodied Robots	暂定 To Be Confirmed
16:05 - 16:30	商务交流 / Networking	

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研讨会日程
Conference Program

2026 粤港澳大湾区机器人创新技术论坛暨粤港澳大湾区机器人科技杰出贡献评选颁奖典礼
2026 GBA Robot Innovation Technology Forum & Award Ceremony for GBA Robot Technology Outstanding Contribution

2026 年 10 月 28 日 7 号馆, 7A90, 具身智能剧院 2
28th October 2026 7A90, Embodied Intelligence Theatre 2, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30 - 09:55	展区参观、会议签到 Exhibition Area Tour & Conference Registration	
10:00 - 10:05	主持人开场介绍、嘉宾介绍 Host Opening Remarks & Guest Introduction	
10:05 - 10:25	【里工】把真实场景的作业经验，转化为可复制的机器人技能 Li-Gong: From Real-World Experience to Replicable Robot Skills	 曹煜然，广州里工实业有限公司，资深市场经理 Fifa Cao, Li-Gong Industrial Co., Ltd., Senior Marketing Manager
10:25 - 10:45	越秀智造赋能企业高质量发展 Yuexiu Intelligent Manufacturing Empowers High-Quality Enterprise Development	 祝思明，越秀 iPARK·粤港云谷，项目总经理 Siming Zhu, Yuexiu iPARK, Project General Manager
10:45 - 11:05	物理智能时代的云端协同算力基础设施 Cloud-based collaborative computing infrastructure in the era of physical intelligence	 张伟豪，非定域科技，博士后研究员 Weihao Zhang, OCTOP, Post doctoral Researcher
11:05 - 11:25	待定 To Be Confirmed	 德智机器人（中国）有限公司 Dezhi Robotics (China) Co., Ltd.
11:25 - 11:45	大会特邀嘉宾 Specially Invited Guest of the Conference	 现场隆重公布 Announced ceremoniously on site
11:45 - 12:05	机器人品牌企业 Robotics Brand Enterprise	演讲主题及嘉宾待定 Presentation Topic & Speaker: To Be Confirmed
12:05 - 13:30	午餐 & 自由交流 Lunch & Networking	
13:30 - 13:35	主持人开场介绍、嘉宾介绍 Host Opening Remarks & Guest Introduction	
13:40 - 14:00	机器人品牌企业 Robotics Brand Enterprise	演讲主题及嘉宾待定 Presentation Topic & Speaker: To Be Confirmed
14:00 - 14:20	水下具身智能的灵巧之手 The Deft Hands of Underwater Embodied Intelligence	 钟稳，恒生智能科技（广州）有限公司，总经理 Wen Zhong, Hengsheng Intelligent Technology (Guangzhou) Co., Ltd., General Manager
14:20 - 14:40	一种蚁式仿生抽血机器人的设计 A Mosquito-Inspired Robotic Design for Blood Sampling	 镇艳，中山大学孙逸仙纪念医院，副教授 Yan Zhen, SUN YAT-SEN MEMORIAL HOSPITAL, SUN YAT-SEN UNIVERSITY Associate Professor

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研讨会议程 Conference Program

14:40 - 15:00	百度具身智能大模型 Baidu Embodied Intelligence Large Model	刘晓辰, 百度公司, 总监 Liu Xiaochen, Baidu, Inc., Director
15:00 - 15:20	演讲主题待定 Presentation Topic: To Be Confirmed	司琛 博士, 优必选战略部经理 / 政府事务部总经理 / 高级战略顾问 Chen Si, Senior Strategic Advisor & GM of Government Affairs, UBTECH Robotics
15:20 - 15:40	机器人产品采购项目分享 Robot Product Procurement Project Sharing	
15:40 - 16:00	“湾区智机, 技创未来” 圆桌会议 "Bay Area Smart Machines, Boundless Scenarios" Roundtable	
16:00 - 16:20	粤港澳大湾区机器人科技杰出贡献评选颁奖典礼 Award Ceremony of the Outstanding Contributions to Robot Technology in the Guangdong-Hong Kong-Macao Greater Bay Area	
16:20 - 16:30	提问环节、交流和嘉宾合影 Q&A, Networking & Group Photo with Guests	

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研讨会日程 Conference Program

2026 具身智能人才培育与产业落地论坛 2026 Embodied Intelligence Talent Development and Industry Implementation Forum

2026 年 10 月 29 日 7 号馆, 7F90, 具身智能剧院 1
29th October 2026 7F90, Embodied Intelligence Theatre 1, Hall 7

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:15	开场致辞 Opening Remarks	 深圳市深汕特别合作区人工智能与机器人产业协会, 庄会长及领导致辞 President Zhuang, Artificial Intelligence and Robotics Industry Association of Shenzhen-Shenshan Special Cooperation Zone
10:15 - 10:30	主旨: 具身智能产业格局与人才战略定调 Keynote: Embodied AI - Industry Landscape and Talent Strategy	 广东省人工智能与机器人学会, 老师 Guangdong Society for Artificial Intelligence and Robotics, Teacher
10:30 - 10:50	高校怎么育——学科体系与产教融合实践 How Universities Cultivate Talent - Disciplinary Systems and Industry-Education Integration	 李蒙, 深圳技术大学 Meng Li, Shenzhen Technology University
10:50 - 11:10	企业怎么育——从“抢人”到“造血” How Companies Cultivate Talent - From "Poaching" to "In-House Development"	 前沿具身企业分享 Leading Embodied AI Company
11:10 - 11:30	人怎么“转身”——跨界人才的职业路径 How Individuals "Pivot" - Career Paths for Cross-Disciplinary Talent	 姜弃疾, 华沿机器人, 副总经理 Qiji Jiang, Huayan Robotics, Deputy General Manager
11:30 - 12:10	圆桌: 产业落地与人才缺口 Roundtable: Industry Deployment vs. Talent Gap	 协会 主持人 + 潜行创新 张莹 + 广东省人工智能与机器人学会 老师 + 深圳技术大学 李蒙 + 投资方 Host, Association + Ying Zhang, QYSEA + Teacher, Guangdong Society for Artificial Intelligence and Robotics + Meng Li, Shenzhen Technology University + Investor
12:10	总结收尾 Closing	 主持人 Host

研讨会日程
Conference Program



深圳机器视觉展暨机器视觉技术及工业应用研讨会
Shenzhen Machine Vision Exhibition and
Machine Vision Technology & Application Conference

2026 年 10 月 27-28 日 9 号馆, 9F66
27th-28th October 2026 9F66, Hall 9

时间 Time	主题 Topic	演讲嘉宾 Speaker
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2026.10.27

大会主题: VISION+AI: 新能源智造中的视觉感知与机器人协同

Theme: VISION+AI: Visual Perception and Robot Collaboration in New Energy Intelligent Manufacturing

10:00 - 10:30	从“被调用”到“自主化”，工业 AI 智能体重构新能源行业生产逻辑 From Invoked Execution to Autonomous Operation: Industrial AI Agents Reshape Production Logic of the New Energy Industry	 刘凯, 思谋科技, 产品总监 Kai Liu, Product Director, SmartMore
10:30 - 11:00	计算成像助力 2.5D 缺陷检测 Computational Imaging for 2.5D Defect Inspection	 李竹纯, 东莞市沃德普自动化科技有限公司, 技术总监 Zhuchun Li, Technical Director, Dongguan Wordop Automation Technology Co., Ltd
11:00 - 11:30	AI 大模型赋能新能源关键工艺智能检测 AI large model empowers intelligent detection of key processes of new energy	 张辉, 阿丘科技, 产品总监 Hui Zhang, Product Director, Aqrose Technology
11:30 - 12:00	从行业趋势到技术需求：共探 AI 数据中心的协同发展 From Industry Trends to Technical Requirements: Exploring Collaboration in AI Data Centers	 王昕, 宝视纳视觉技术(北京)有限公司, 产品市场经理 Sean Wang, Product Marketing Manager, Basler
12:00 - 13:30	午休 / Lunch Break	

AI 与 3D 视觉驱动的机器人应用实践

AI and 3D Vision-Driven Robotic Application Practices

13:30 - 14:00	从具身视觉识别到业务闭环：多模态大模型与智能体赋能工厂数智化 From Embodied Visual Recognition to Closed-Loop Operations: How Multimodal Large Models and AI Agents Empower Smart Factories	 乔玉川, 上海商汤智能科技有限公司, 解决方案总监 Yuchuan Qiao, Director of Solutions, Shanghai SenseTime Intelligent Technology Co., Ltd.
14:00 - 14:30	AI+ 具身智能：驱动工业机器人智能化升级 AI + Embodied Intelligence: Driving the Intelligent Upgrade of Industrial Robots	 付翱, 梅卡曼德(雄安)机器人科技股份有限公司, 联合创始人兼业务副总裁 Ao Fu, Co-founder and VP of Business Development, Mech-Mind Robotics Technologies Co., Ltd.
14:30 - 15:00	3D 视觉前沿进展及具身应用实践 3D Vision Frontiers and Embodied Applications in Practice	 费浙平, 上海图漾光学科技有限公司, CEO Felix Fei, CEO, Percipio Technology Ltd.
15:00 - 15:30	视觉智能体覆盖整厂视觉的原理与实践 Vision Agents for Factory-Wide Visual Intelligence: Principles and Practice	 崔忠伟, 北京领邦智能装备股份公司, 董事长 Zhongwei Cui, Chairman, Beijing Leadbang Intelligent Equipment Co., Ltd.
15:30 - 16:00	从感知到决策：面向智能制造的 AI 视觉引导架构 From Perception to Decision: AI Vision-Guided Architecture for Intelligent Manufacturing	 包瑞, 北京叁博视界人工智能科技有限公司, CEO Rui Bao, CEO, Beijing Sanbo Vision Artificial Intelligence Technology Co., Ltd
16:00 - 17:00	参观展览会 / Visit the Exhibition	

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研讨会议程 Conference Program

VISION CHINA
Shenzhen 2026
深圳机器视觉展

2026.10.28

大会主题：VISION+AI：新能源智造中的视觉感知与机器人协同

Theme: VISION+AI: Visual Perception and Robot Collaboration in New Energy Intelligent Manufacturing

AI 机器视觉在半导体精密检测中的应用与挑战

Applications and Challenges of AI Machine Vision in Semiconductor Precision Inspection

10:00 - 10:30	算力浪潮下：精密测量传感器与仪器赋能光模块及半导体量产突围 Under the wave of computing power: precision measurement sensors and instruments empower mass production of optical modules and semiconductors to break through	唐磊，光子（深圳）精密科技有限公司，全球销售总监 Lei Tang, Global Sales Director, Phoskey (Shenzhen) Precision Technology Co., Ltd.
10:30 - 11:00	线扫检测在半导体先进封装 AOI 中的应用 Application of Line Scan Inspection in Advanced Semiconductor Packaging AOI	范福永，瓊荔德（上海）光学仪器有限公司，销售总监 Antonio Fan, Head of Sales of China, Allied Vision
11:00 - 11:30	突破“卷”局：智能 2D+3D 视觉组合赋能检测创新 Breaking Through: Smart 2D+3D Vision Synergy for Inspection & Measurement Innovation	李裕荣，LMI Technologies，战略客户经理 Edwin Li, Strategic Account Manager, LMI Technologies
11:30 - 12:00	半导体封装行业的 AI 检测与量测技术 AI-Powered Inspection and Metrology for the Semiconductor Packaging Industry	冯小磊，德律科技，副理 Xiaolei Feng, Deputy Manager, Test Research, Inc. (TRI)
12:00 - 13:30	午休 / Lunch Break	
13:30 - 14:00	微光向芯，智检进阶：面向 SMT、光互联与半导体封装的 AOI 技术演进 AOI Technology Evolution for SMT, Optical Interconnection and Semiconductor Packaging	李鑫，快克智能装备股份有限公司，销售总监 Xin Li, Sales Director, QUICK INTELLIGENT EQUIPMENT CO., LTD.
14:00 - 14:30	光模块视觉检测技术发展现状和应用实践 Development Status and Application Practice of Optical Module Vision Inspection Technology	丰徐华，东莞康视达自动化科技有限公司，高级应用工程师 Xuhua Feng, Senior Application Engineer, Dongguan CST Automation Technology Co., Ltd.
14:30 - 15:00	创新型工业相机助力半导体封装产业革新 Innovative Industrial Cameras Driving Innovation in Semiconductor Packaging and Testing	吴熙思，深圳市度申科技有限公司，方案工程师 Xisi Wu, Solution Engineer, D03THINK
15:00 - 15:30	大恒图像在半导体行业视觉成像产品的应用实践与案例分析 Application Practice and Case Analysis of Daheng Imaging in Visual Imaging Products of Semiconductor Industry	史风光，大恒图像，产品经理 Fengguang Shi, Product Manager, Daheng Imaging
15:30 - 17:00	参观展览会 / Visit the Exhibition	

* 部分演讲嘉宾，实际名单以现场公布为准

* Some speakers are listed; the actual list is subject to on-site announcement.



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Scan the QR code to follow the
[Vision Machine Vision Exhibition]
WeChat official account to learn the latest agenda.

研讨会议程
Conference Program



“芯”选型·智造升级·国产芯——智能终端与端侧 AI 技术应用论坛
"Chip" Selection · Intelligent Manufacturing Upgrade · Domestic Chips
- Forum on Intelligent Terminals and Edge AI Technology Applications

2026 年 10 月 27 日 15 号馆, 一号会议室
27th October 2026 Hall 15, Meeting Room 1

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30 - 10:00	签到交流 Check-in & Discussion	
10:00 - 10:10	主办方致辞 Organizer's Address	深圳市电子商会、慧聪电子网 SECC, HC360 Electronics Network
10:10 - 10:40	《2026 国产晶振行业调研报告》核心观点发布暨国产元器件选型圆桌对话 Release of Core Insights from the 2026 Domestic Crystal Oscillator Industry Research Report & Roundtable Dialogue on Domestic Component Selection	泰晶科技、晶科鑫、汇隆晶片、广东惠伦、采购方代表 T-King, Jinkexin, Huilong Wafer, Guangdong Huilun, Representatives of Purchasers
10:40 - 11:00	《从通信模组到 AI 智能体：移远通信的汽车电子布局》 From Communication Modules to AI Agents: Quectel's Automotive Electronics Layout	汪衍, 上海移远通信技术股份有限公司, 产品总监 Wang Kan, Product Director, Quectel
11:00 - 11:20	《从买方视角看车规芯片：选型标准与国产替代的真实决策逻辑》 Automotive-Grade Chips from the Buyer's Perspective: Selection Criteria and the Real Decision-Making Logic of Domestic Substitution	张华, 原中兴通讯供应链总监 Zhang Hua, Former Supply Chain Director of ZTE Corporation
11:20 - 11:40	《从导航设备厂商的视角, 看车规芯片的选型与国产化适配》 From the Perspective of Navigation Device Manufacturers: Automotive-Grade Chip Selection and Localization Adaptation	纪亮章, 广东百福达电子科技有限公司, 总经理 Ji Liangzhang, General Manager, Guangdong Baifuda
11:40 - 12:00	大合影、抽奖 Group Photo & Lucky Draw	

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研讨会议程 Conference Program



第二届国产芯片技术创新与市场应用论坛 The 2nd Domestic Chip Technology Innovation and Market Application Forum

2026 年 10 月 27 日 15 号馆, 一号会议室
27th October 2026 Hall 15, Meeting Room 1

时间 Time	主题 Topic	演讲嘉宾 Speaker
13:00 - 13:30	签到交流 Check-in & Discussion	
13:30 - 13:35	主持开场介绍 Host Opening & Introduction	
13:35 - 14:00	2026 国产 AI 芯片市场格局与产业趋势研判 2026 Domestic AI Chip Market Landscape and Industry Trend Analysis	刘西妹, 华强电子产业研究所, 高级研究员 Liu Ximei, Senior Researcher, Huaqiang Electronics Industry Research Institute
14:00 - 14:25	从芯片到生态: 华为昇腾 / 鲲鹏算力介绍 From Chips to Ecosystem: Introduction to Huawei Ascend / Kunpeng Computing Power	华为 Huawei
14:25 - 14:50	MCU 矩阵如何赋能 AI 算力基础设施 / AI 边缘智能硬件的全栈式落地之道 How the MCU Matrix Empowers AI Computing Infrastructure / Edge AI Intelligent Hardware: The Path to Full-Stack Deployment	芯海科技 Chipsea Technologies
14:50 - 15:15	存储「新变量」: 定义 AI 终端新边界 Storage's New Variables: Redefining Boundaries of AI Terminals	梁槐花, 康芯威存储, 市场规划部总经理 Liang Huaihua, General Manager of Marketing Planning Department, Kangxinwei Storage
15:15 - 15:40	算力跃升背后的电容力量——MLCC 在 GPU 与数据中心供电系统中的应用与技术演进 The Capacitor Force Driving Computing Surge: MLCC Applications and Technical Evolution in GPU & Data Center Power Systems	谭斌, 微容科技, 首席技术专家 Tan Bin, Chief Technical Expert, VIYONG Technology
15:40 - 16:05	智算时代的心跳——高端光模块时钟器件的国产化突破 Heartbeat of the Intelligent Computing Era: Domestic Breakthroughs of High-End Timing Devices for Optical Modules	詹超, 泰晶科技, 技术中心副主任 Zhan Chao, Deputy Director of Technology Center, TKD
16:05 - 16:10	抽奖 / 问答 / 合影 Lucky Draw, Q&A & Group Photo	

研讨会议程
Conference Program



芜湖电子产业交流会
Wuhu Electronics Industry Forum

2026 年 10 月 27 日 15 号馆, 二号会议室
27th October 2026 Hall 15, Meeting Room 2

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:30	主持开场介绍 Host Opening & Introduction	
09:30 - 09:35	深圳市电子商会领导致辞 Remarks by Leader of SECC	 徐慧英, 深圳市电子商会常务副会长、秘书长 Xu Huiying, Executive Vice President & Secretary-General, SECC
09:30 - 09:45	芜湖市高新区(弋江区)领导致辞 Remarks by Leader of Wuhu Hi-tech Industrial Development Zone (Yijiang District)	 余靖, 弋江区委常委、统战部部长 Yu Jing, Member of the Standing Committee of the Yijiang District Party Committee and Head of the United Front Work Department
09:45 - 10:00	芜湖市人才发展集团领导致辞 Remarks by Leader of Wuhu Talent Development Group	 陆照海, 芜湖市人才发展集团党委副书记、总经理 Lu Zhaohai, Deputy Secretary of the Party Committee and General Manager of Wuhu Talent Development Group
10:00 - 10:15	芜湖高新区投资环境推介 Wuhu Hi-tech Zone Investment Promotion	 谭思敏, 芜湖市高新区投资促进部, 副部长 Tan Simin, Deputy Director of the Investment Promotion Department, Wuhu High-tech Zone
10:15 - 10:30	芜湖紫云英人才政策推介 Promotion of Wuhu Ziyunying Talent Program	
10:30 - 11:30	高层次人才项目路演 High-Level Talent Project Roadshow	1. 深圳市佑泽电子汽车电子元器件销售中心项目 2. 可锐电子热敏、压敏电阻研发项目 3. 济德精密汽车连接器生产项目 4. 科力尔汽车电机有限公司华东研发中心项目 5. 斯多福胶水华东运营中心项目 6. 索威尔科技喷涂机器人项目 7. 迈步机器人外骨骼助力机器人项目
11:30 - 12:00	产业链上下游对接 Upstream and Downstream Industry Chain Matchmaking	

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研讨会议程 Conference Program



数据驱动·AI 赋能——电子元器件原厂竞争力重构创新论坛 Data-Driven · AI-Empowered - Innovation Forum on Restructuring the Competitiveness of Electronic Component Original Manufacturers

2026 年 10 月 27 日 15 号馆, 二号会议室
27th October 2026 Hall 15, Meeting Room 2

时间 Time	主题 Topic
14:00-14:30	签到 Check-in
14:30-14:35	介绍参会领导及嘉宾 Introduction of Attending Leaders and Guests
14:35-14:55	广州泊沧数据技术有限公司领导致辞 Remarks by Leader of Bocang Data 深圳市电子商会领导致辞 Remarks by Leader of SECC
14:55-15:15	国创基础资源库：筑牢 AI 时代工业智能化的数据底座 Guochuang Basic Resource Library: Building the Data Foundation for Industrial Intelligence in the AI Era
15:15-15:30	猎芯网：从设计选型到供应链采购 IC600: From Design & Selection to Supply Chain Procurement
15:30-15:45	深思造物：AI 驱动电子制造与终端产品智能化创新 Sishi Creation: AI-Driven Innovation in Electronic Manufacturing and Intelligent End Products
15:45-16:00	英码科技：实验证数据 +AI 升级的可量化实践成果 EMA: Quantifiable Practical Outcomes of Validated Data & AI Upgrade
16:00-16:15	DesignPulse：国创基础资源库赋能 AI 设计，驱动电子设计新范式 DesignPulse: Guochuang Basic Resource Library Empowers AI Design, Driving a New Paradigm for Electronic Design
16:15-16:25	抽奖互动 Lucky Draw & Interaction
16:25-17:00	茶歇交流 Coffee Break & Networking

研讨会日程 Conference Program



2026 汽车电子与电源专场采购对接会 2026 Automotive Electronics & Power Supply Special Procurement Matchmaking Conference

2026 年 10 月 27 日 15 号馆，国内采购对接区
27th October 2026 Hall 15, Domestic Procurement Matching Zone

时间 Time	采购企业名单 List of Purchasing Enterprises	现场对接人 On-site Contact Person
10:00 - 12:00	云鲸智能创新(深圳)有限公司 NARWAL Intelligence Innovation (Shenzhen) Co., Ltd.	采购 Purchasing
	深圳市百泰实业股份有限公司 SHENZHEN BOOMTECH INDUSTRY SHARES CO., LTD.	供应链总监 Supply Chain Director
	东莞市安瑞创智能科技有限公司 Dongguan Anycon Intelligent Technology Co., Ltd.	采购经理 Purchasing Manager
	追觅科技(苏州)有限公司 Dreame Technology (Suzhou) Co., Ltd.	高级采购经理 Senior Purchasing Manager
	东莞市东颂电子有限公司 Dongguan Dongsong Electronic Co., Ltd.	采购经理 Purchasing Manager
	深圳福微芯电科技有限公司 Shenzhen Fuway Tech Technology Co., Ltd.	采购经理 Purchasing Manager
	深圳拓邦股份有限公司 Shenzhen Topband Co., Ltd.	采购 Purchasing
	金龙机电股份有限公司 Jinlong Machinery & Electronic Co., Ltd.	采购经理 Purchasing Manager
	深圳逗点生物技术有限公司 Shenzhen Biocomma Biotechnology Co., Ltd.	供应链总监 Supply Chain Director
	中山市美苏电器有限公司 Zhongshan Meisu Electrical Appliances Co., Ltd.	采购经理 Purchasing Manager
	敬业集团有限公司 Jingye Group Co., Ltd.	采购专员 Purchasing Specialist
	广州舒客科技有限公司 Guangzhou Saky Technology Co., Ltd.	采购经理 Purchasing Manager
	深圳斯特普科技有限公司 Shenzhen Stepp Technology Co., Ltd.	采购主管 Purchasing Supervisor
	深圳市亚米拉电子科技有限公司 Shenzhen Amira Electronic Technology Co., Ltd.	采购主管 Purchasing Supervisor
	深圳市鑫汇科股份有限公司 SHENZHEN CHK CO., LTD.	计划采购部部长 Minister of Planning & Purchasing Department
	广东新佳盟电子科技有限公司 Guangdong Lemark Electronics Technology Co., Ltd.	电子开发采购 Electronic Development Procurement
	广东新佳盟电子科技有限公司 Guangdong Lemark Electronics Technology Co., Ltd.	电子开发采购 Electronic Development Procurement
	深圳市鑫汇科股份有限公司 SHENZHEN CHK CO., LTD.	电子开发采购 Electronic Development Procurement
	广东宗隆电子科技有限公司 Guangdong Zonglong Electronic Technology Co., Ltd.	采购副总 Vice President of Purchasing
	深圳贝斯格朗科技有限公司 Shenzhen Best Grinder Technology Co., Ltd.	采购经理 Purchasing Manager

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研讨会议程 Conference Program



AI 算力及液冷技术生态合作大会 AI Computing Power and Liquid Cooling Technology Ecosystem Cooperation Conference

2026 年 10 月 28 日 15 号馆, 二号会议室
28th October 2026 Hall 15, Meeting Room 2

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:30 - 10:40	嘉宾及观众签到入场 Check-in & Admission for Guests and Audience	
10:40 - 10:50	主持人介绍嘉宾 / 领导致辞 Host Introduces Guests / Leaders' Address	
10:50 - 11:10	区块链赋能液冷 AIDC Blockchain Empowered Liquid-Cooled AIDC	 深圳市链力液冷设备技术有限公司 LIANLI
11:10 - 11:30	AI 算力液冷散热全链路测试验证解决方案 End-to-End Test & Validation Solution for AI Computing Power Liquid Cooling	 东莞市杰创电子测控科技有限公司 JIECHUANG
11:30 - 11:50	面向未来电力系统应用的超级电容发展探析 Analysis on the Development of Supercapacitors for Future Power System Applications	 陕西合创时代科技有限公司 HECHUANG
11:50 - 12:30	互动交流 Q&A Session	 现场嘉宾与观众商务对接交流 On-site Business Matching between Guests and Audience
12:30	午餐 / 自由观展 Lunch & Free Exhibition Visit	

研讨会议程 Conference Program



淮南电子产业交流会 Huainan Electronic Industry Exchange Conference

2026 年 10 月 29 日 15 号馆, 一号会议室
29th October 2026 Hall 15, Meeting Room 1

时间 Time	主题 Topic	演讲嘉宾 Speaker
09:00 - 09:30	嘉宾签到 Guest Check-in	
09:30 - 09:40	开场致辞 Opening Address	
09:40 - 10:40	淮南电子信息产业链专题推介 Special Promotion of Huainan Electronic Information Industry Chain	淮南市、经开区、高新区 Huainan City, Economic & Technological Development Zone, Hi-Tech Zone
10:40 - 11:30	重点企业路演 Roadshow of Key Enterprises	芯视佳、和亿德及深圳代表企业 Cignature, Heyide and Representative Enterprises from Shenzhen
11:30 - 12:00	政企面对面、产业链供需一对一洽谈交流 Government-Enterprise Face-to-Face & One-on-One Matching Negotiation for Industry Chain Supply and Demand	
12:00	活动结束 Event Concludes	

亚洲工业科技展·蓝点奖颁奖典礼 Industrial Technology World Asia · Blue Dot Awards Ceremony

2026 年 10 月 29 日 15 号馆, 二号会议室
29th October 2026 Hall 15, Meeting Room 2

时间 Time	主题 Topic	演讲嘉宾 Speaker
10:00 - 10:30	嘉宾签到 Guest Check-in	
10:30 - 12:00	亚洲工业科技展·蓝点奖颁奖 Industrial Technology World Asia · Blue Dot Awards Presentation	

具体会议日程请以会议现场演讲为准, 解释权归主办单位所有。
The agenda is subject to change without prior notification. RX reserves the right of final interpretation.